

# THE IDEA VERTEX DETECTOR AND ITS INTEGRATION IN THE FCC-EE INTERACTION REGION

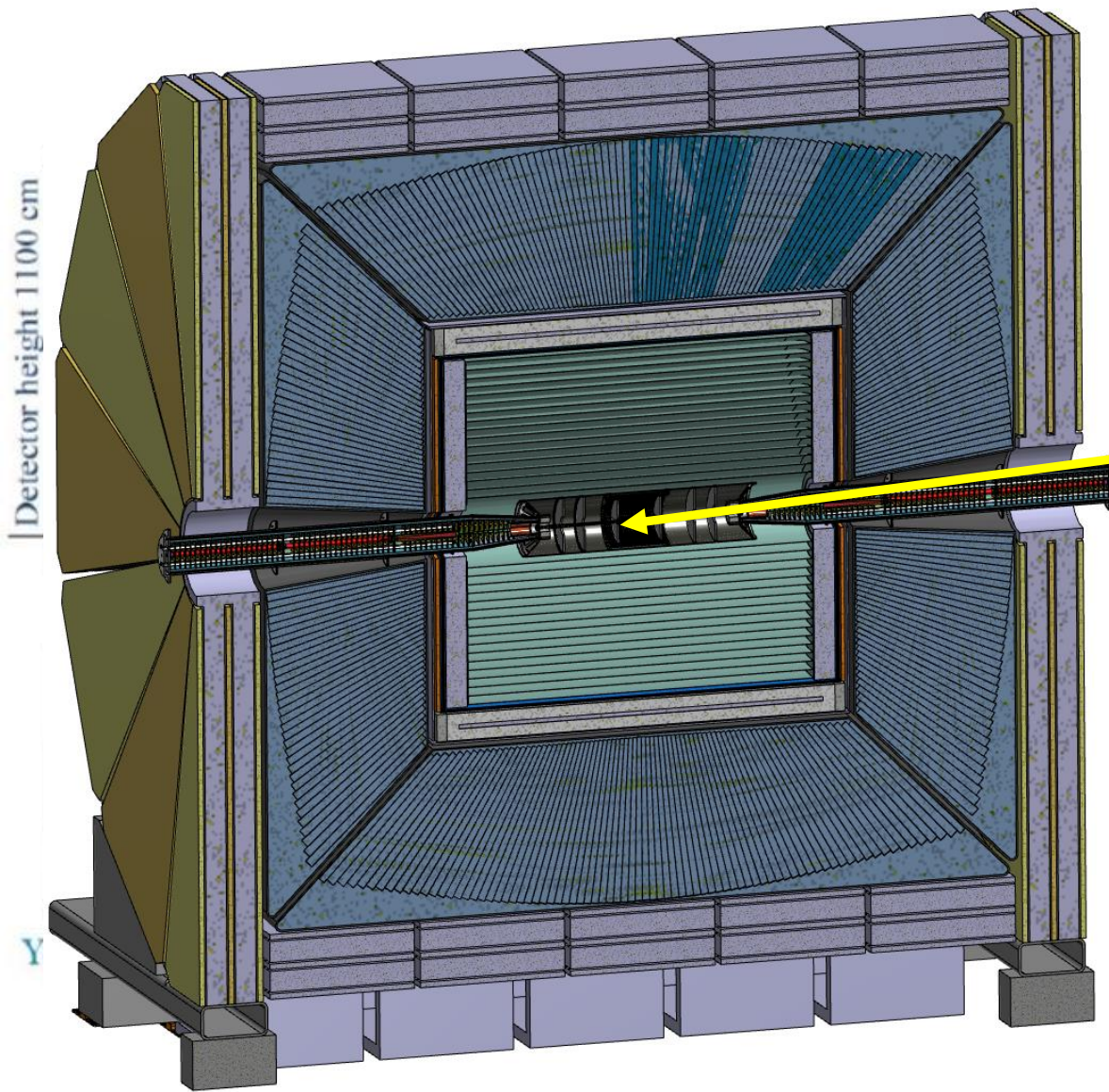
**Fabrizio Palla<sup>1</sup>**

Manuela Boscolo<sup>2</sup>, Filippo Bosi<sup>1</sup>, Francesco Franesini<sup>2</sup>, Stefano Lauciani<sup>2</sup>

<sup>1</sup>INFN Sezione di Pisa, Italy

<sup>2</sup>INFN Laboratori Nazionali di Frascati (RM), Italy

*Joint DC & SW meeting  
31 July 2023*



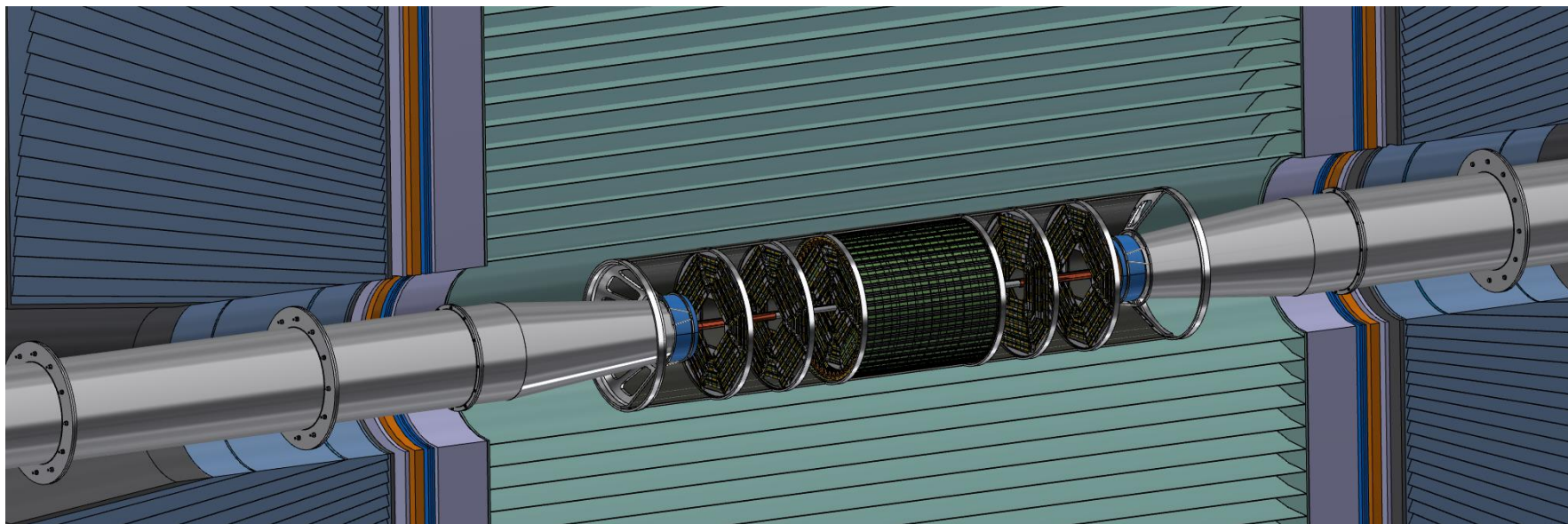
- Central tracking device:
  - light Drift CHamber
- **Silicon detectors for precision measurements**
  - vertex detector
  - silicon internal tracker
  - silicon wrapper
- Thin solenoid with 2T field (according to MDI limits)
- Dual readout calorimeter
  - supplemented by a pre-shower detector
- Muon chambers in the solenoid return yoke

# Requirements

Interaction region detectors must be integrated with the beam pipe

- The vertex detector innermost radius should profit of the reduced beam pipe diameter (2 cm) and should cover  $|\cos\theta| < 0.99$
- **Must not interfere with the Luminosity Calorimeter (clearance of ~120 mrad)**
- **The mounting of the vertex tracker must be done inside the support tube**
- Minimize the radiation lengths

# Inner and outer vertex trackers



Inside the same volume of the support tube that holds also the LumiCal

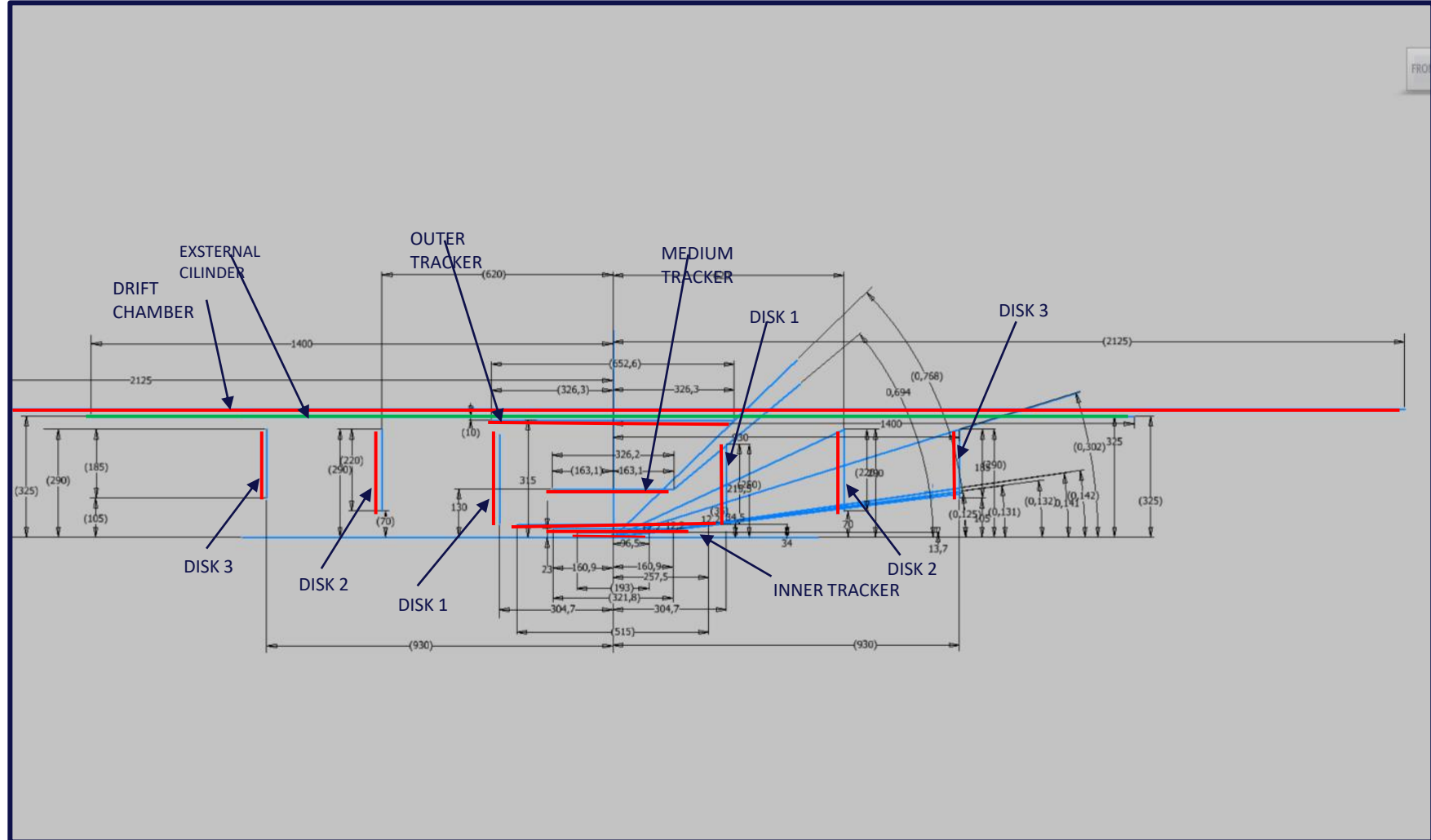
**Inner vertex detector supported by the beam pipe**

**Outer vertex detector (2 barrel and 6 disks) fixed to the support tube**

**Minimal number of detector module variants**

**One module type only for the Vertex**

**One module type only for the Outer barrel and disks**



**Outer vertex tracker:**

Modules of  $50 \times 150 \mu\text{m}^2$  pixel size

- Intermediate barrel at 13 cm radius (improved reconstruction for  $p_T > 40$  MeV tracks)
- Outer barrel at 31.5 cm radius
- 3 disks per side

**Inner Vertex detector:**

Modules of  $25 \times 25 \mu\text{m}^2$  pixel size

3 barrel layers at

- 13.7, 22.7 and 33 mm radius

# Inner vertex detector modules



Based on ARCADIA INFN R&D

## Depleted Monolithic Active Pixel Detectors (DMAPS)

Technology: LF11is 110 nm CMOS node, high-resistivity bulk

Pixel size  $25 \times 25 \mu\text{m}^2$ , 50  $\mu\text{m}$  thick

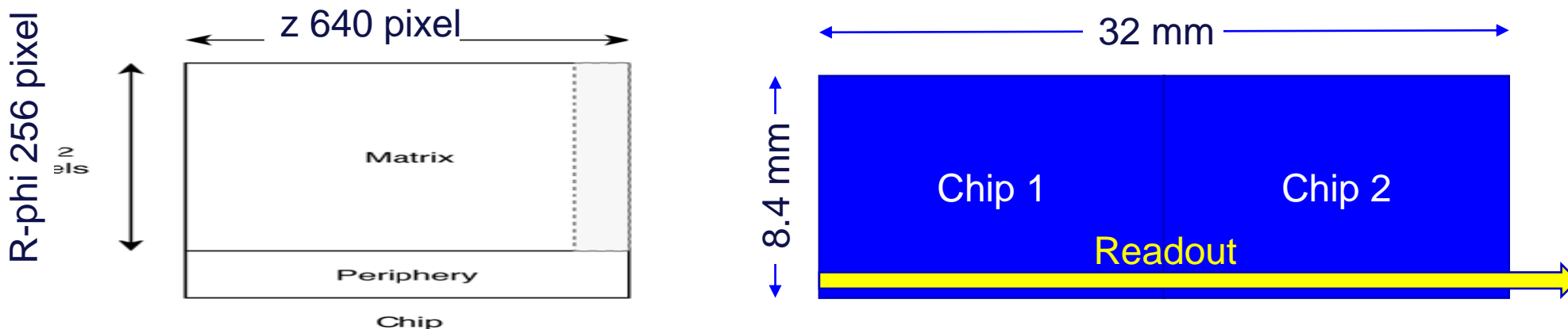
Active area 640 pixel (16 mm) in  $z$  and 256 pixels (6.4 mm) in  $r - \varphi$

Chip periphery plus an inactive zone: total of 2 mm in  $r - \varphi$

Chips are side-abutable in  $z$

Modules composed of 2 sensors: total of 8.4 mm ( $r - \varphi$ )  $\times$  32 mm ( $z$ )

Power budget: assume  $50 \text{ mW}/\text{cm}^2$  - including power and readout buses

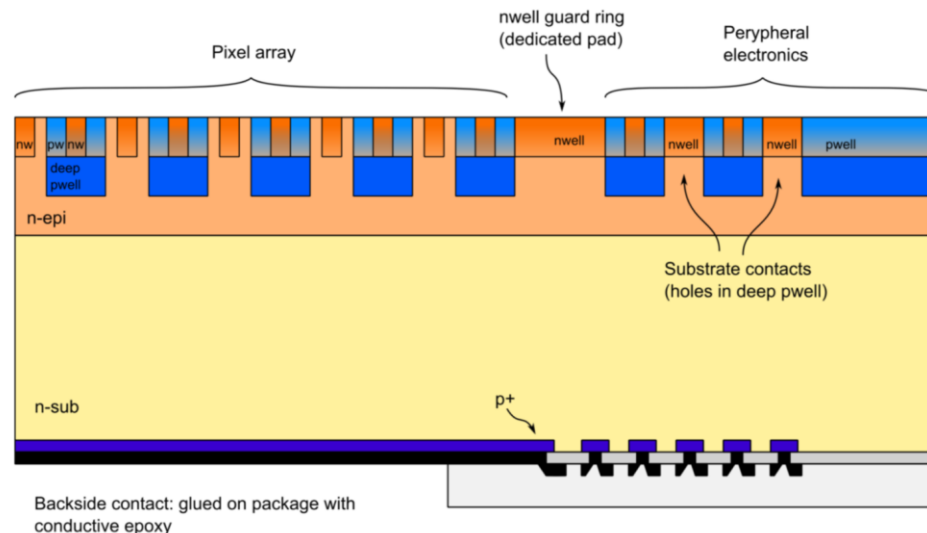


# ARCADIA DMAPS R&D at INFN

Advanced Readout CMOS Architectures with Depleted Integrated sensor Arrays

Fully Depleted Monolithic Active Pixel CMOS sensor technology platform allowing for:

- \* Active sensor thickness in the range 50  $\mu\text{m}$  to 500  $\mu\text{m}$  or more;
- \* Operation in full depletion with fast charge collection by drift, small collecting electrode for optimal signal-to-noise ratio;
- \* Scalable readout architecture with ultra-low power capability ( $O(10 \text{ mW/cm}^2)$ );
- \* Compatibility with standard CMOS fabrication processes
- \* Technology: LF11is 110nm CMOS node (quad-well, both PMOS and NMOS), high-resistivity bulk
- \* Custom patterned backside, patented process developed in collaboration with LFoundry



# ARCADIA

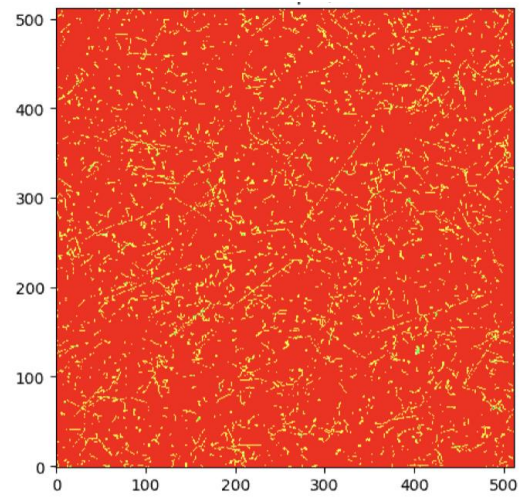
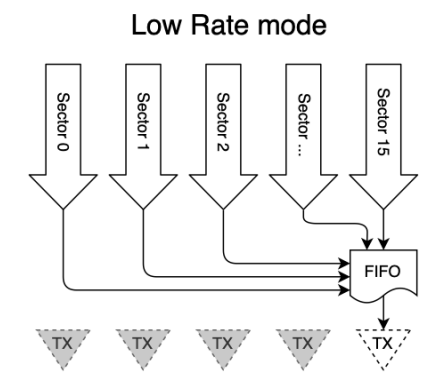
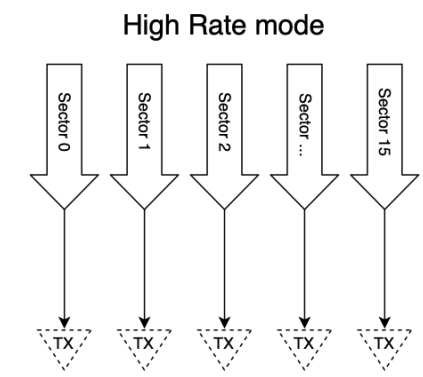
"Fully Depleted MAPS in 110-nm CMOS Process With 100–300- $\mu\text{m}$  Active Substrate," in IEEE Transactions on Electron Devices, June 2020, doi: [10.1109/TED.2020.2985639](https://doi.org/10.1109/TED.2020.2985639).

# ARCADIA R&D

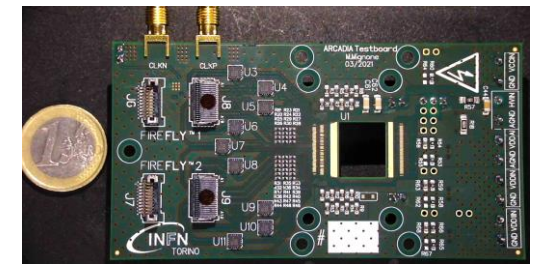
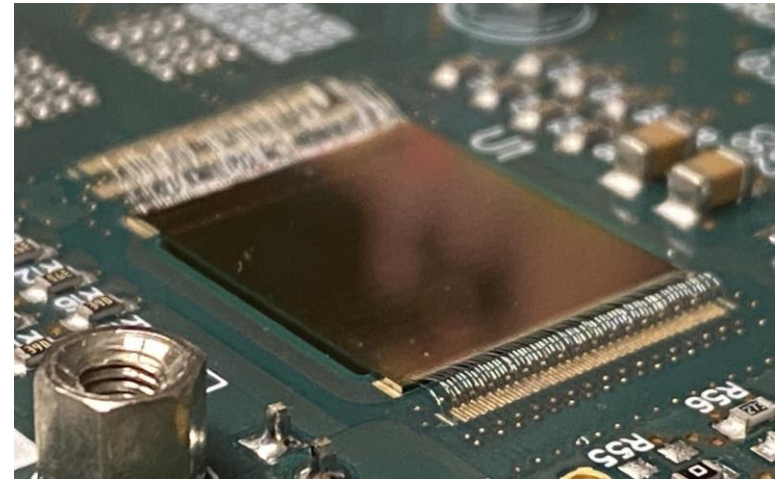
- ✳ Sensor R&D and Technology, CMOS IP Design and Chip Integration, Data Acquisition and Characterisation
- ✳ 3 engineering runs with full-scale FD-DMAPS and sensor R&D (monolithic FD-strips and readout, fast sensors with gain layer)
- ✳ High rate capability (100 MHz/cm<sup>2</sup>) architecture on a scalable 512x512 pixel matrix (25um pitch) MD3 Main Demonstrator chip:
  - ▶ **measured 30 mW/cm<sup>2</sup>** at full-speed (16 data Tx active) and **10 mW/cm<sup>2</sup>** on low-rate mode (1 data Tx active)



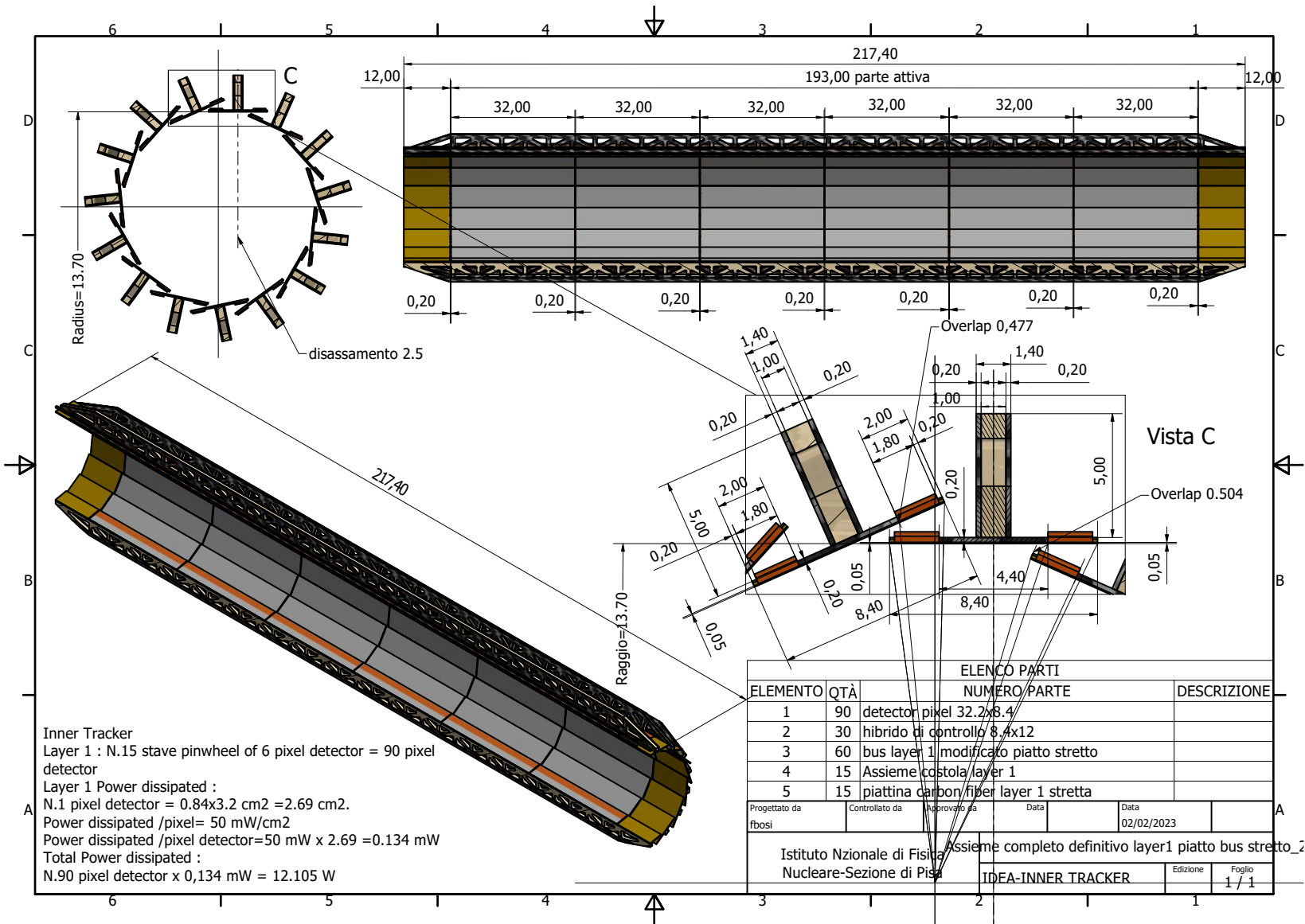
Istituto Nazionale di Fisica Nucleare



Cosmic ray data







Inner Tracker  
 Layer 1 : N.15 stave pinwheel of 6 pixel detector = 90 pixel detector  
 Layer 1 Power dissipated :  
 N.1 pixel detector = 0.84x3.2 cm2 = 2.69 cm2.  
 Power dissipated /pixel= 50 mW/cm2  
 Power dissipated /pixel detector=50 mW x 2.69 =0.134 mW  
 Total Power dissipated :  
 N.90 pixel detector x 0,134 mW = 12.105 W

**Layer 1**  
 15 overlapping staves of 6 modules each  
 Overlap to allow alignment ~500 μm  
 Pinwheel geometry: all modules at the same (smallest) radius  
 Power budget ~12 W  
 Total weight ~22 grams  
 Total thickness 0.25%  $X_0$   
 Silicon: 0.053%  $X_0$   
 Power and readout bus: 0.056%  $X_0$

ELENCO PARTI			
ELEMENTO	QTÀ	NUMERO/PARTE	DESCRIZIONE
1	90	detector pixel 32.2x8.4	
2	30	ibrido di controllo 8.4x12	
3	60	bus layer 1 modificato piatto stretto	
4	15	Assieme costola layer 1	
5	15	piattina carbon fiber layer 1 stretta	

Progettato da	Controllato da	Approvato da	Data
fbosi			02/02/2023

Istituto Nazionale di Fisica Nucleare-Sezione di Pisa

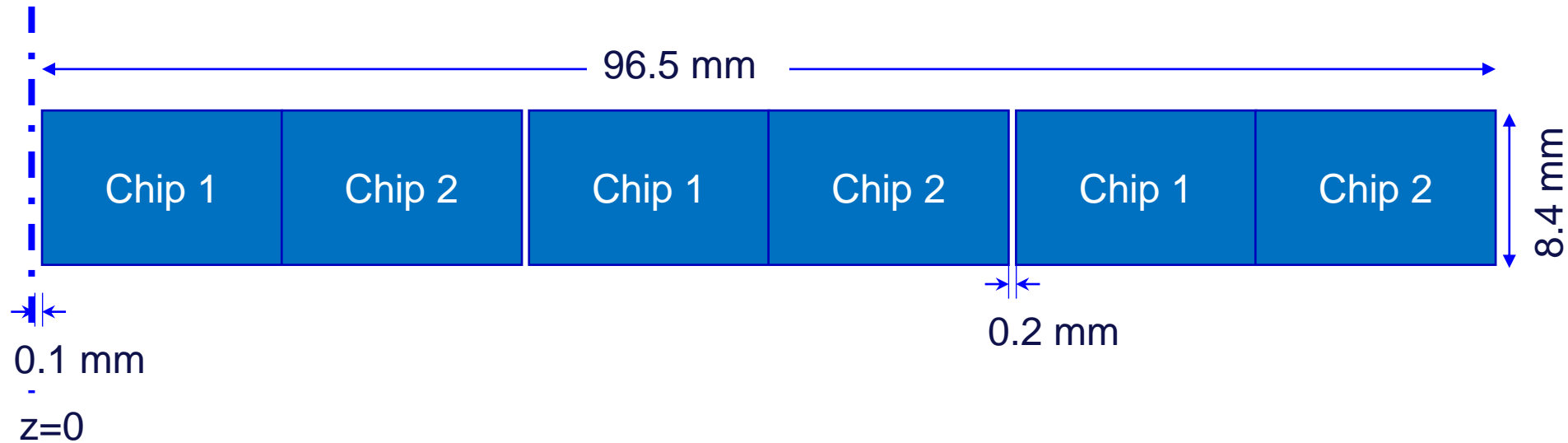
Assieme completo definitivo layer1 piatto bus stretto\_2

IDEA-INNER TRACKER

Edizione 1 / 1

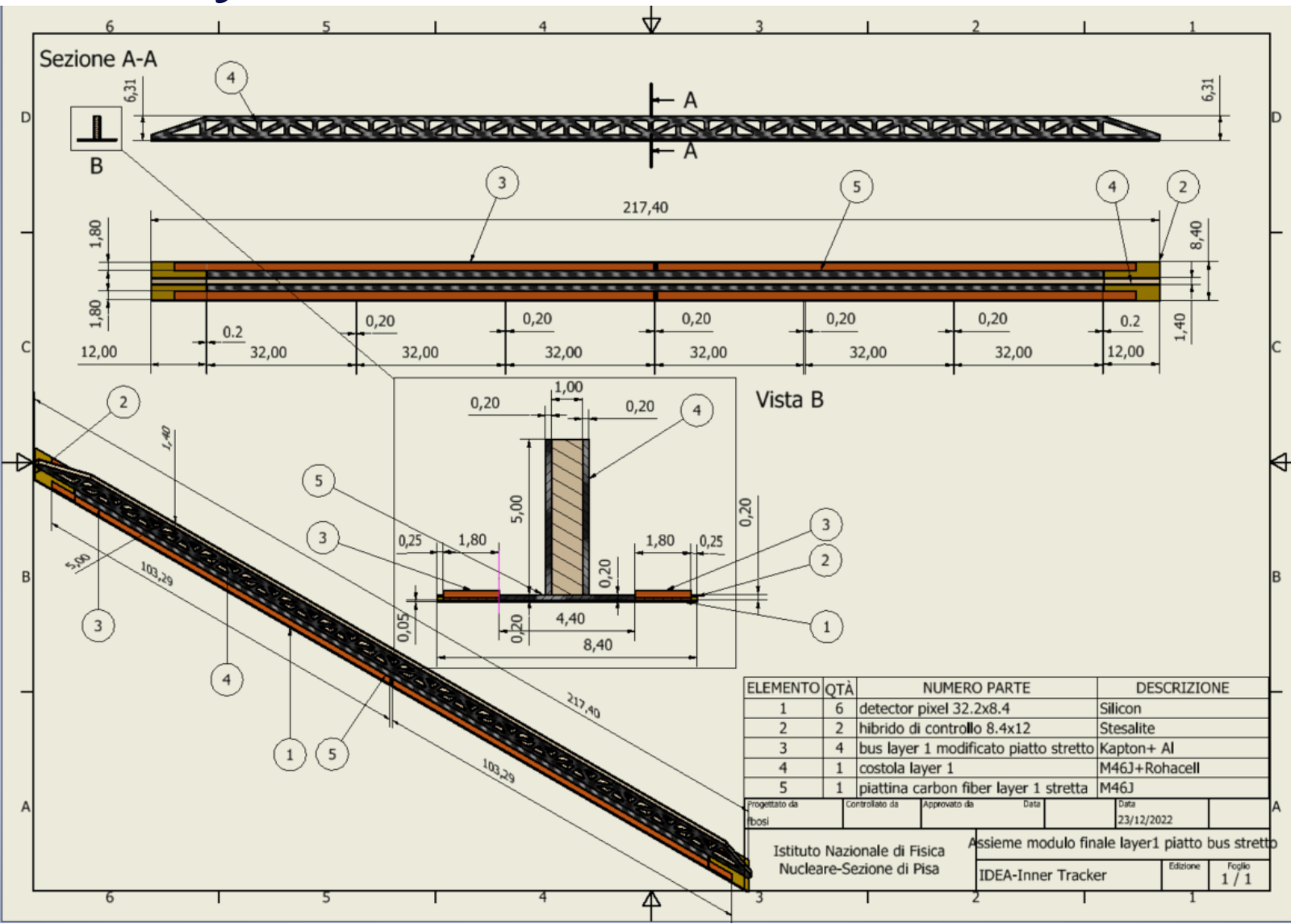
Foglio 1 / 1

# Half-ladder layout – layer 1



Layer 1 ladders are placed at 13.7 mm radius

# Layer 1 stave detail



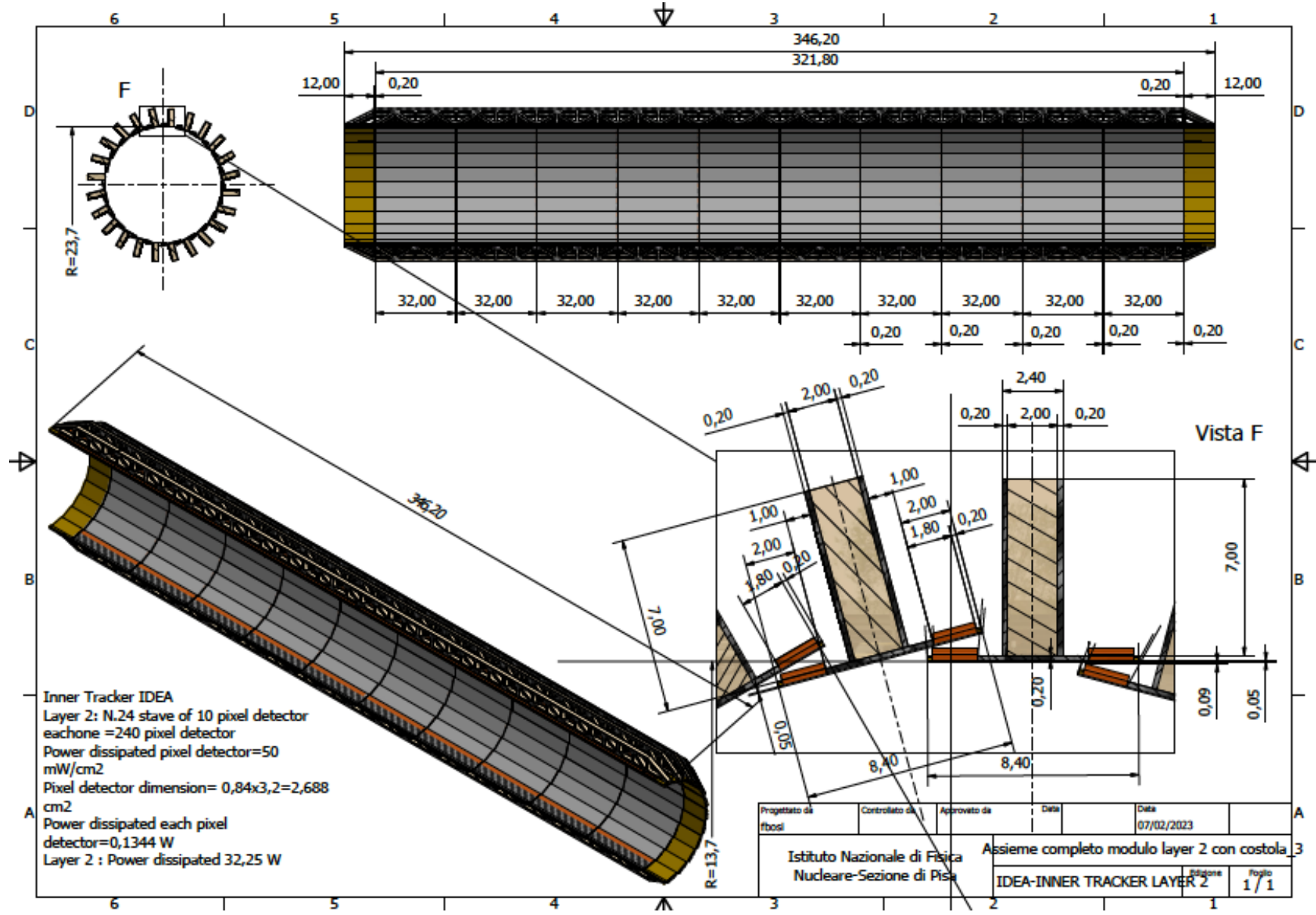
Reticular lightweight support to provide stiffness

- Thin carbon fiber walls interleaved with Rohacell
- 2 buses (data and power) 1.8 mm wide and 250 μm thick (50 μm Al, 200 μm kapton) per side
  - Inspired to low mass hybrid R&D

Sensors facing interaction point w/o any other material in front

Readout chips either sides

Air cooled



Inner Tracker IDEA  
 Layer 2: N.24 stave of 10 pixel detector  
 eachone =240 pixel detector  
 Power dissipated pixel detector=50  
 mW/cm<sup>2</sup>  
 Pixel detector dimension= 0,84x3,2=2,688  
 cm<sup>2</sup>  
 Power dissipated each pixel  
 detector=0,1344 W  
 Layer 2 : Power dissipated 32,25 W

Progettato da fposi	Controllato da	Approvato da	Data 07/02/2023
Istituto Nazionale di Fisica Nucleare-Sezione di Pisa		Assemble completo modulo layer 2 con costola	
IDEA-INNER TRACKER LAYER 2		Edizione 1/1	Foglio 1/1

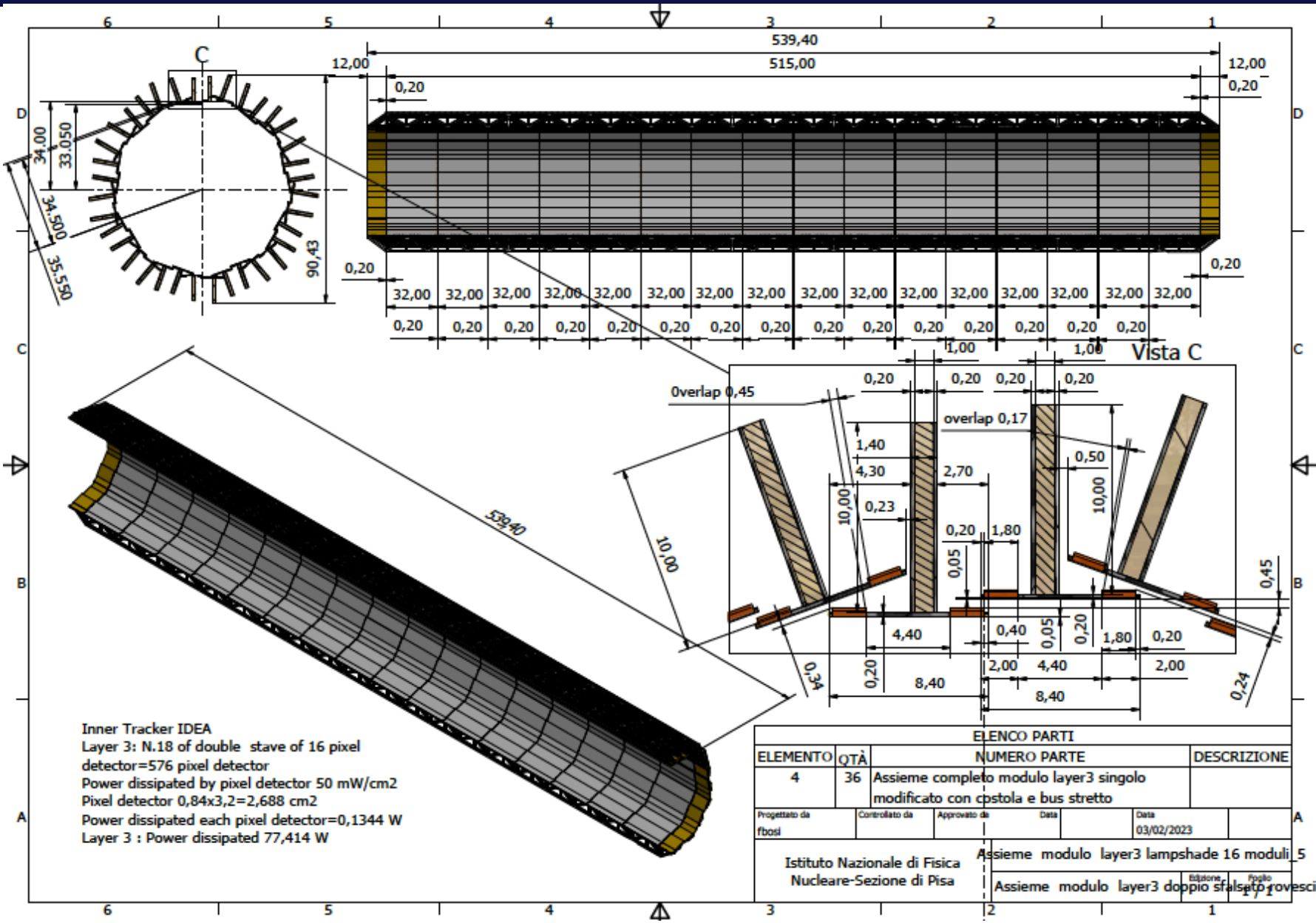
**Layer 2**  
 24 overlapping staves of  
 10 modules each

Pinwheel geometry  
 Counter-rotated wrt layer  
 1 to mitigate charge-  
 asymmetry effects in  
 track reconstruction

Power budget  
 ~32 W

Total weight ~63 grams

Total thickness 0.25% X<sub>0</sub>

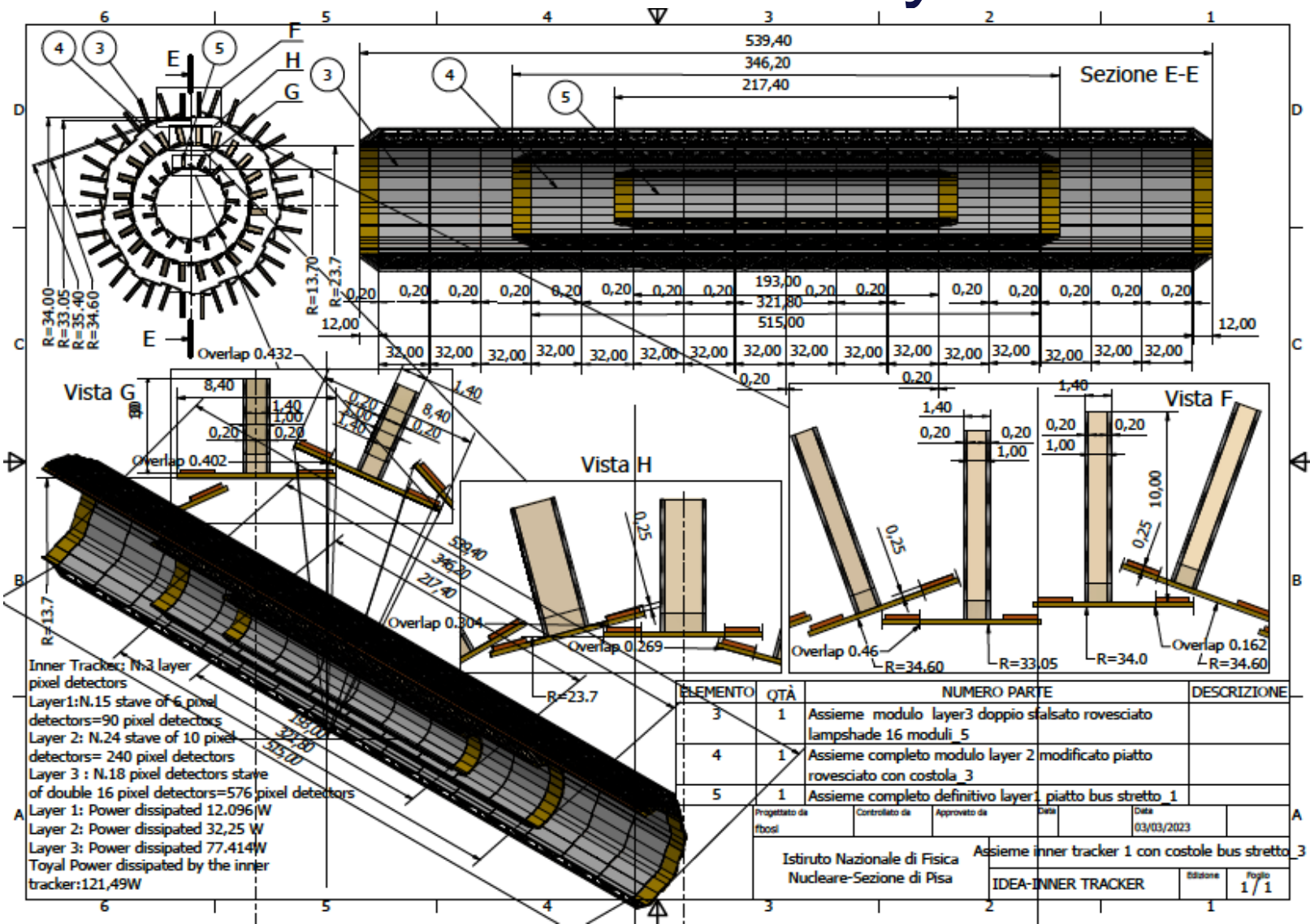


Inner Tracker IDEA  
 Layer 3: N.18 of double stave of 16 pixel detector=576 pixel detector  
 Power dissipated by pixel detector 50 mW/cm2  
 Pixel detector 0,84x3,2=2,688 cm2  
 Power dissipated each pixel detector=0,1344 W  
 Layer 3 : Power dissipated 77,414 W

ELENCO PARTI													
ELEMENTO	QTÀ	NUMERO PARTE	DESCRIZIONE										
4	36	Assieme completo modulo layer3 singolo modificato con cpstola e bus stretto											
<table border="1"> <tr> <td>Progettato da</td> <td>Controllato da</td> <td>Approvato da</td> <td>Data</td> <td>Data</td> </tr> <tr> <td>fbosi</td> <td></td> <td></td> <td></td> <td>03/02/2023</td> </tr> </table>				Progettato da	Controllato da	Approvato da	Data	Data	fbosi				03/02/2023
Progettato da	Controllato da	Approvato da	Data	Data									
fbosi				03/02/2023									
Istituto Nazionale di Fisica Nucleare-Sezione di Pisa		Assieme modulo layer3 lampshade 16 moduli	5										
		Assieme modulo layer3 doppio sfalsato rovesci	1										

**Layer 3**  
 18 overlapping staves of double 16 modules each  
 Lampshade geometry.  
 Charge symmetric track reconstruction  
 Total weight ~150 grams  
 Total thickness 0.25% X<sub>0</sub>  
 Power budget ~77 W

# Overall Inner Vertex layout



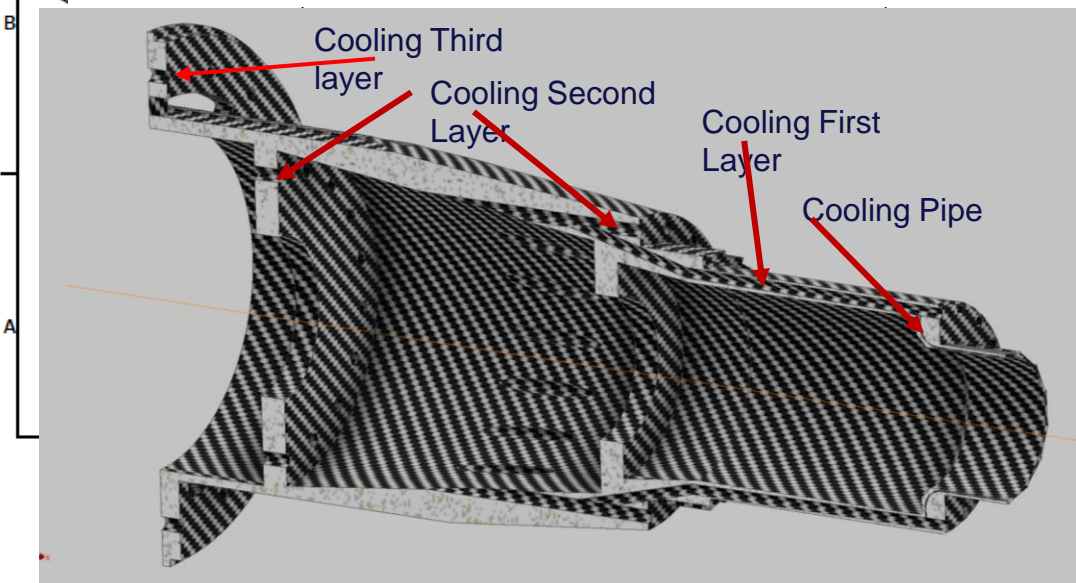
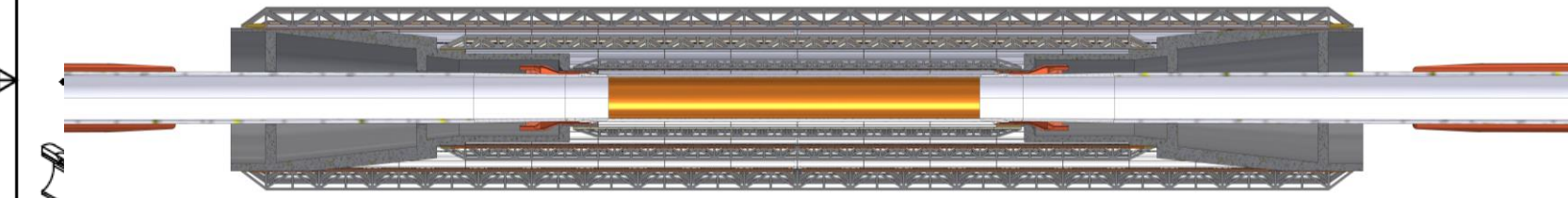
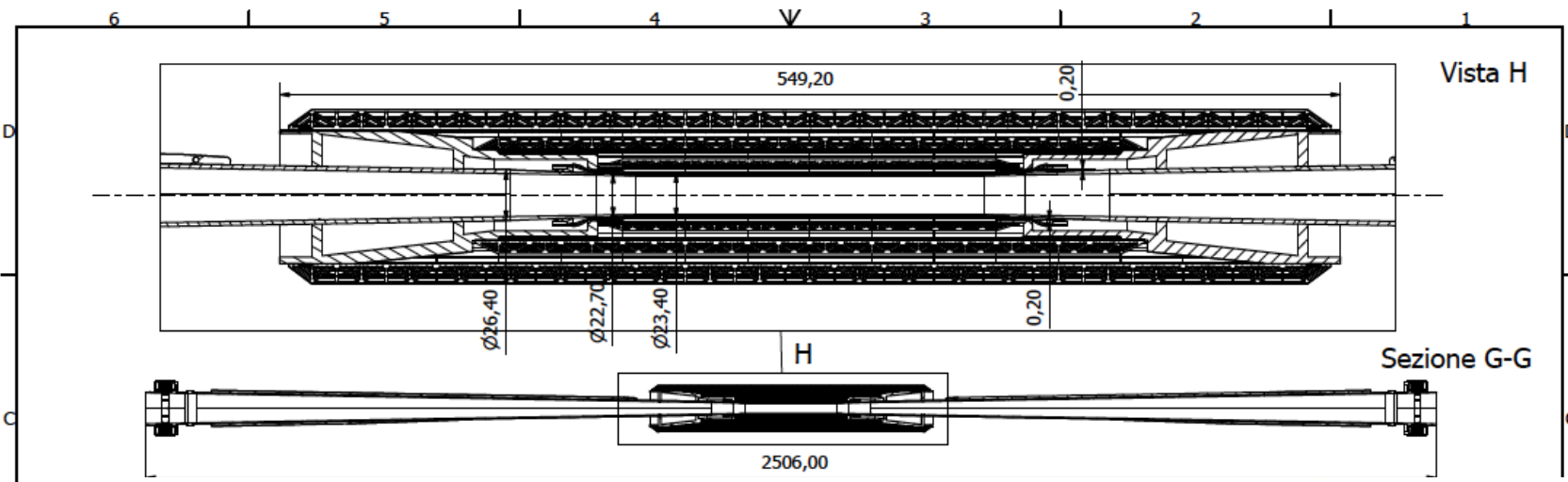
**Total power ~120 W**  
**Total weight ~230 grams**

Progettato da fbocci	Controllato da	Approvato da	Data	Data
Istituto Nazionale di Fisica Nucleare-Sezione di Pisa		Assieme inner tracker 1 con costole bus stretto 3		
IDEA-INNER TRACKER		Edizione	Pagina 1 / 1	



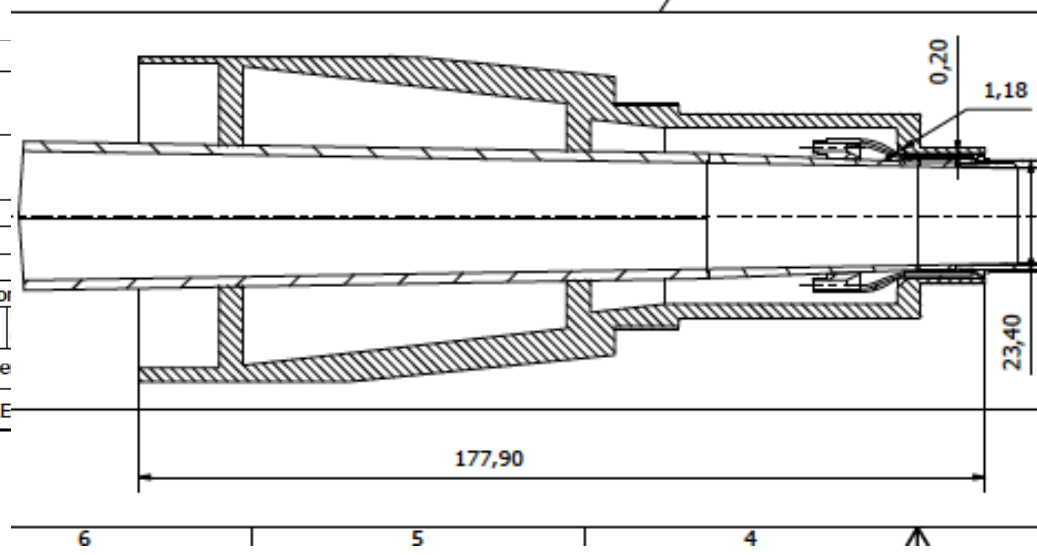
Inner vertex detector supporting conical structures on elliptical chamber  
~450 grams

Engineered for air ducts and thermal isolation from the beam pipe during bakeout



978,40

ELENCO PARTI	
NUMERO PARTE	
chamber_27012023	
Assieme inner tracker con supporti carboni	
Controllato da	Approvato da
chamber_27012023+inne	
IDEA-INNER TRACKE	



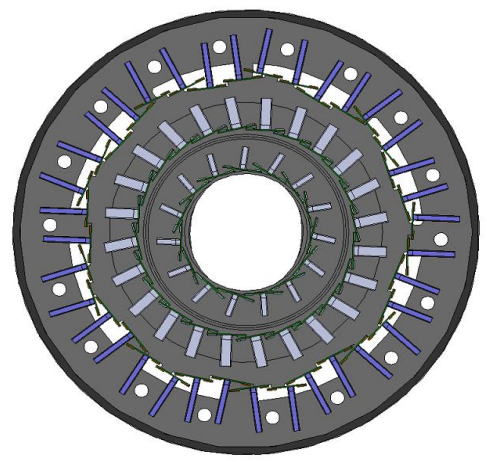
# Thermal simulation started

Start from a radial sector of layer 3 (relying on periodic symmetry) and import in ANSYS FEA. Then move to all other layers  
Layer 3 is the toughest in power dissipation and length

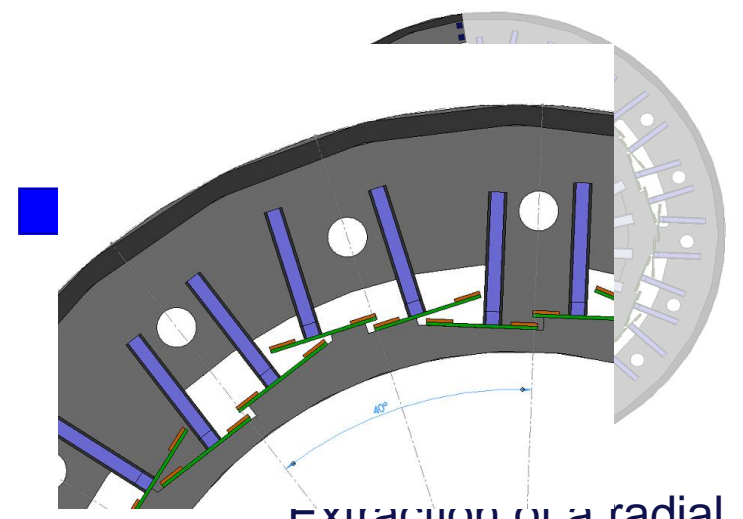
INFN Perugia

G. Baldinelli, F. Bianchi, C. Turrioni

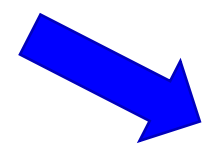
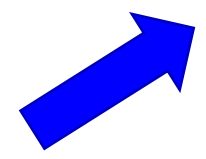
## FIRST STEPS



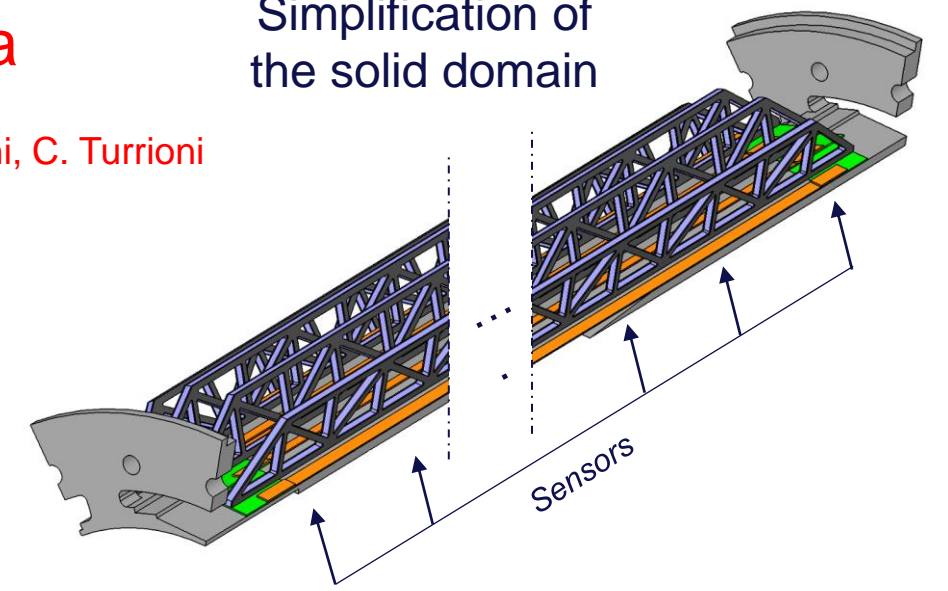
Full model



Extraction of a radial sector for layer 3



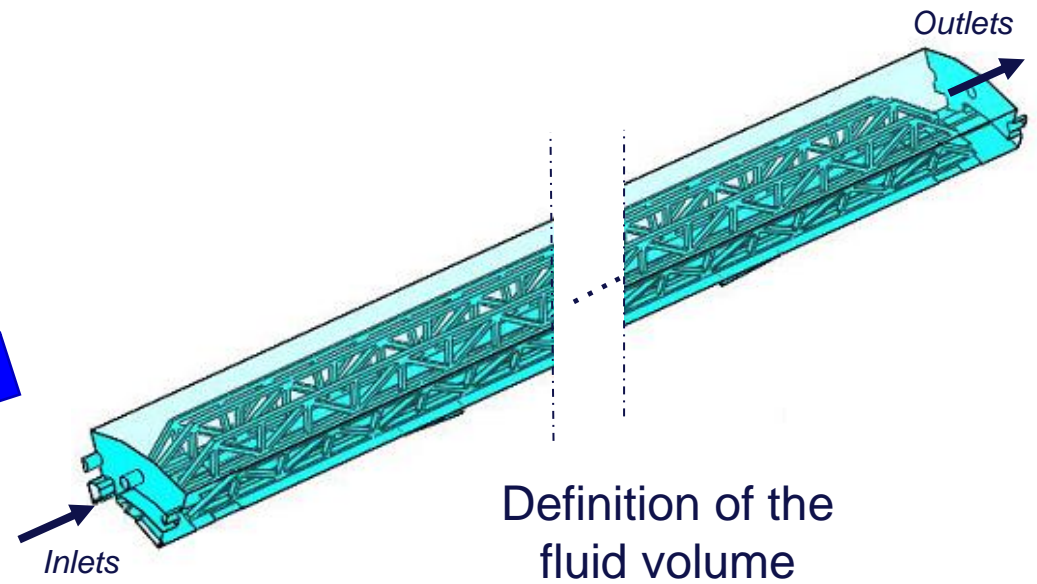
Simplification of the solid domain



Sensors

Outlets

Definition of the fluid volume



Inlets

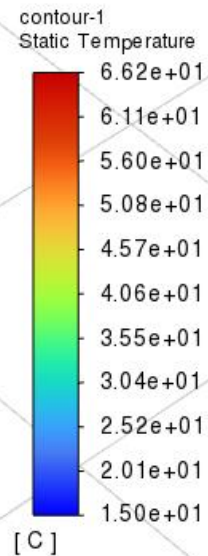


# Preliminary results – simulations

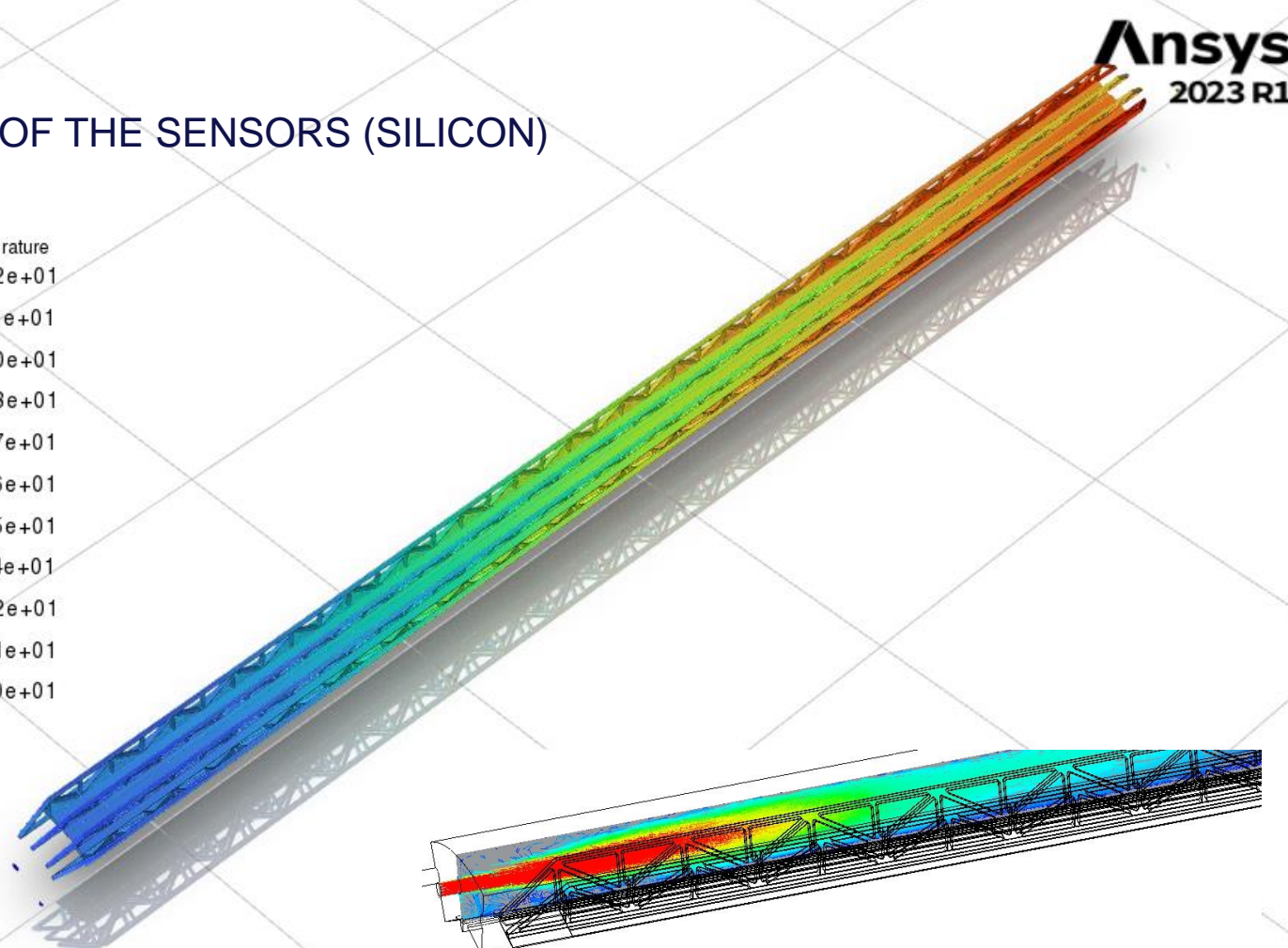


Ansys  
2023 R1

TEMPERATURE OF THE SENSORS (SILICON)



Air at 15°C – 20 m/s



Maximum temperature = +66°C

Air velocity drops to 10 m/s inside (from 20 m/s)

Thermal figure of merit: 66-15 = 51°C

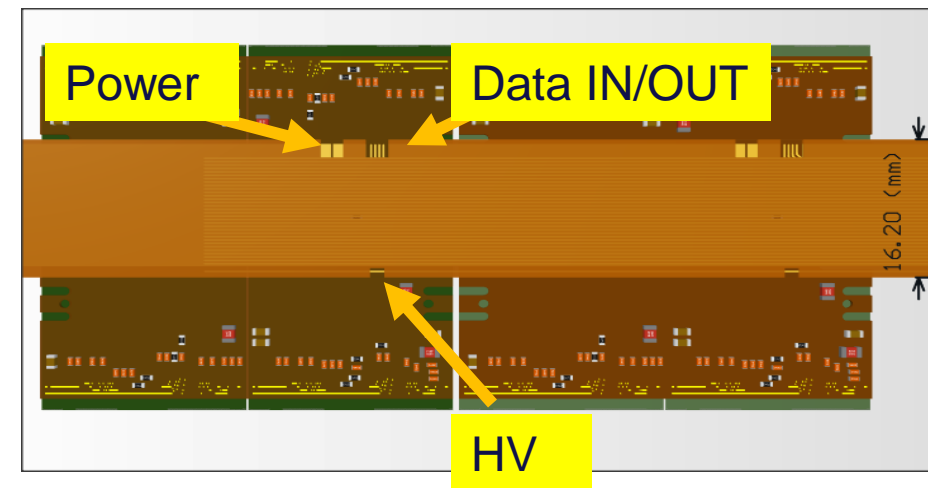
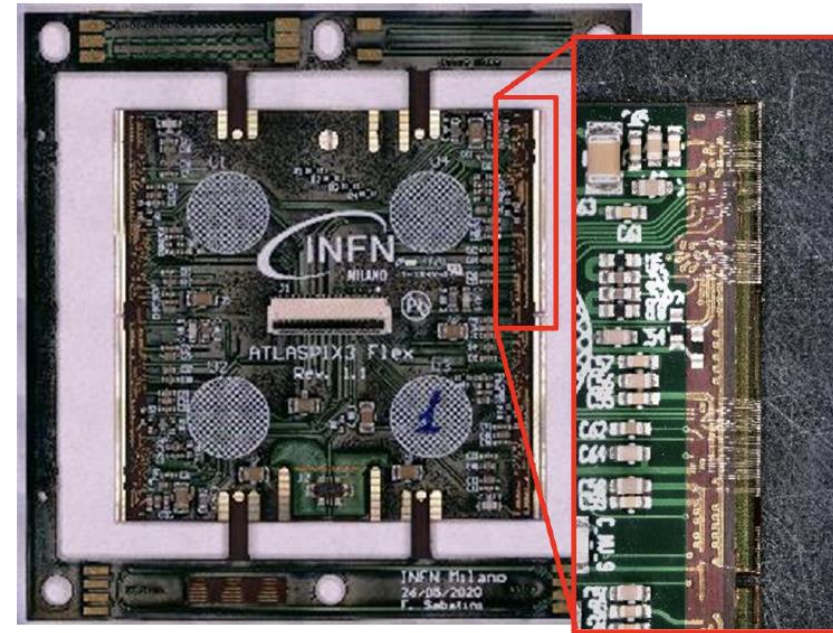
Linear behaviour

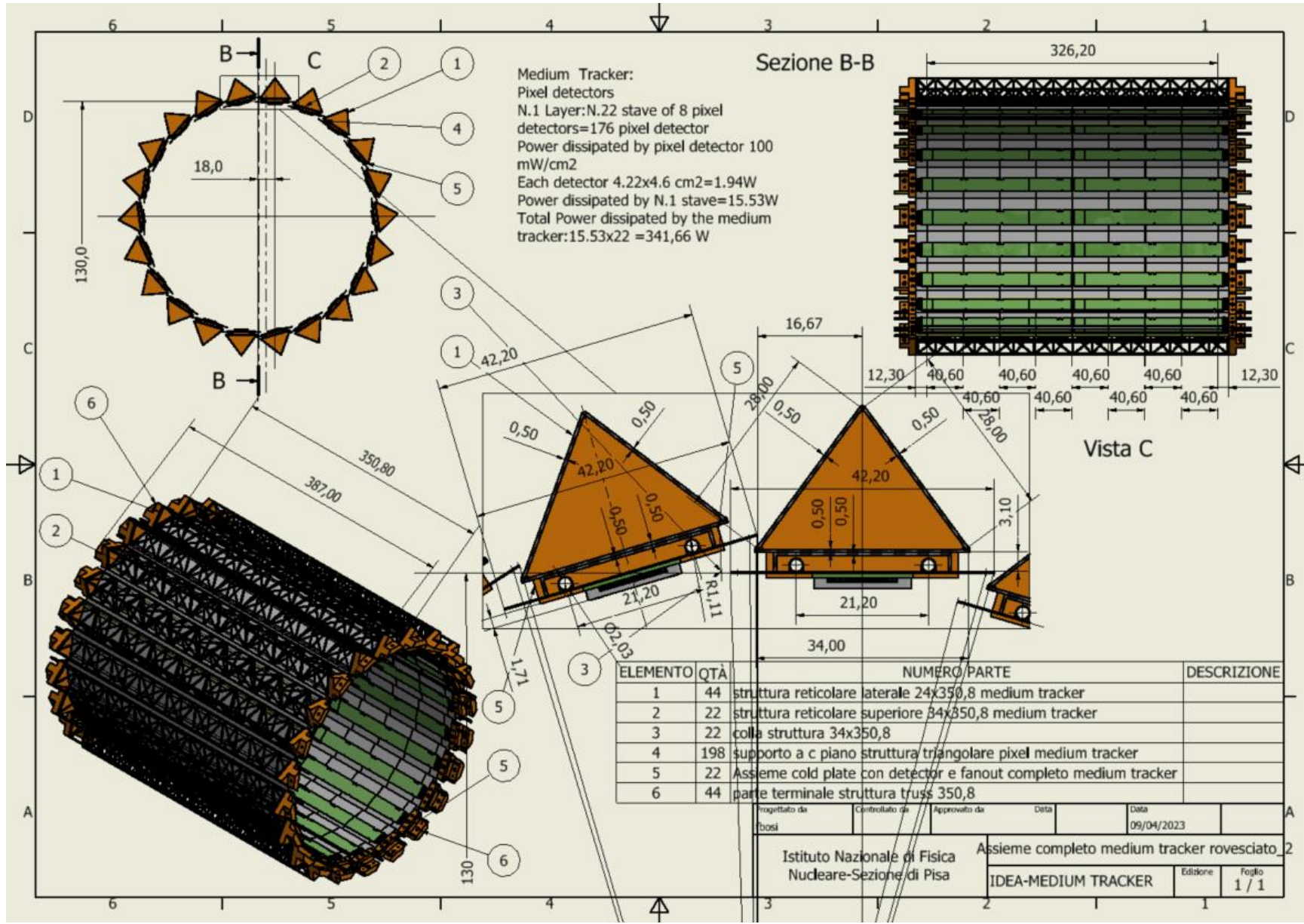
Feeding holes diameter is 2.5 mm too small → next try 6 mm (>5x flux increase)

# Outer vertex layers modules

Based on ATLASPIX3 R&D

- DMAPS
- $50 \times 150 \mu\text{m}^2$
- Up to 1.28 Gb/s downlink
- TSI 180 nm process
- 132 columns of 372 pixels
  
- Active (total) length (r-phi x z)
  - 18.6 (21) mm x 19.8 (20.2) mm
- Module is made of 2x2 chips – total length:
  - size 42.2 mm x 40.6 mm
  
- Power budget not established yet:  
 assume  $100 \text{ mW}/\text{cm}^2$





**Middle Vertex Barrel**  
**At 13 cm radius**

22 staves of 8 modules each.

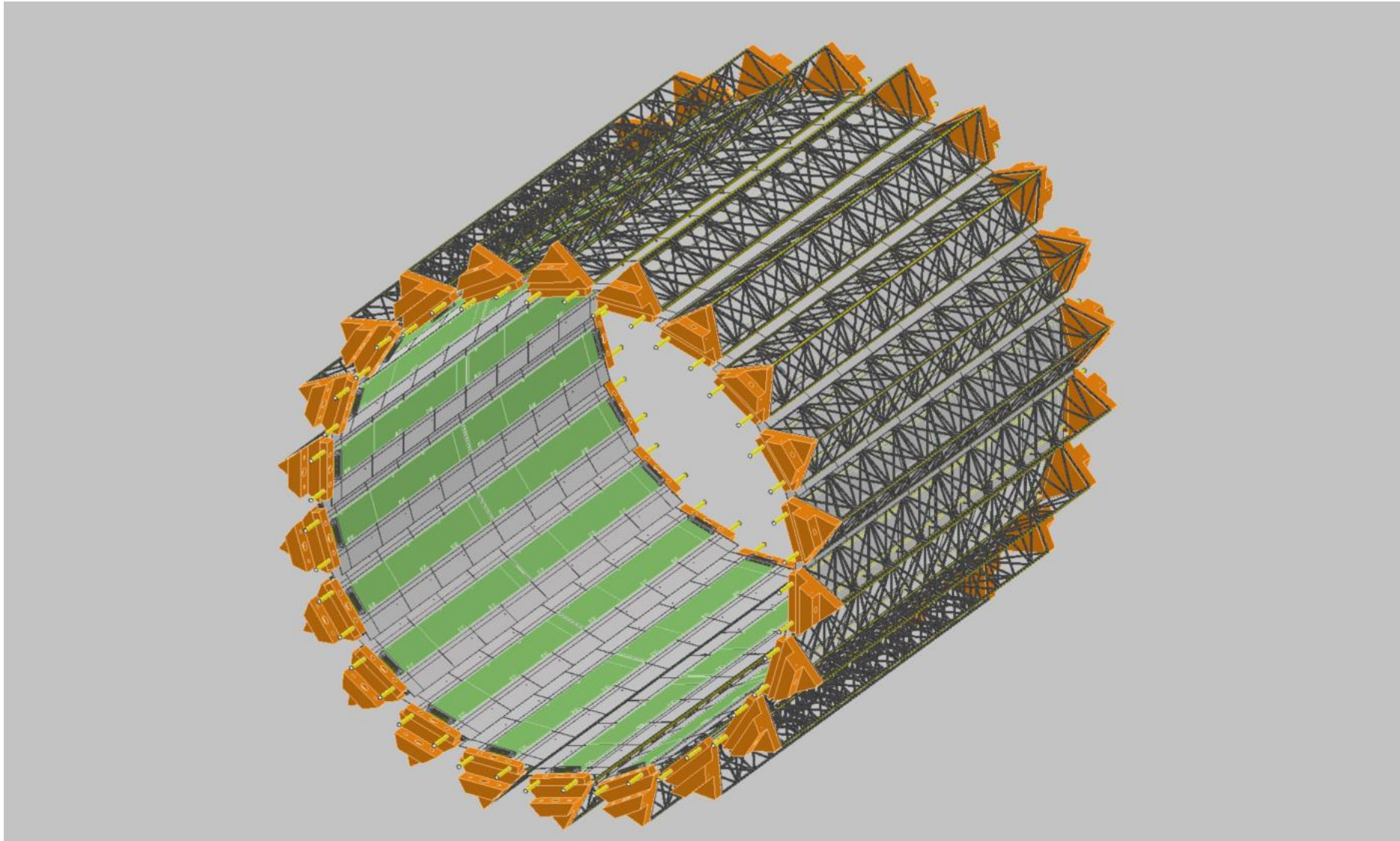
Lightweight reticular support structure (ALICE/Belle-II like)

Readout chips either side

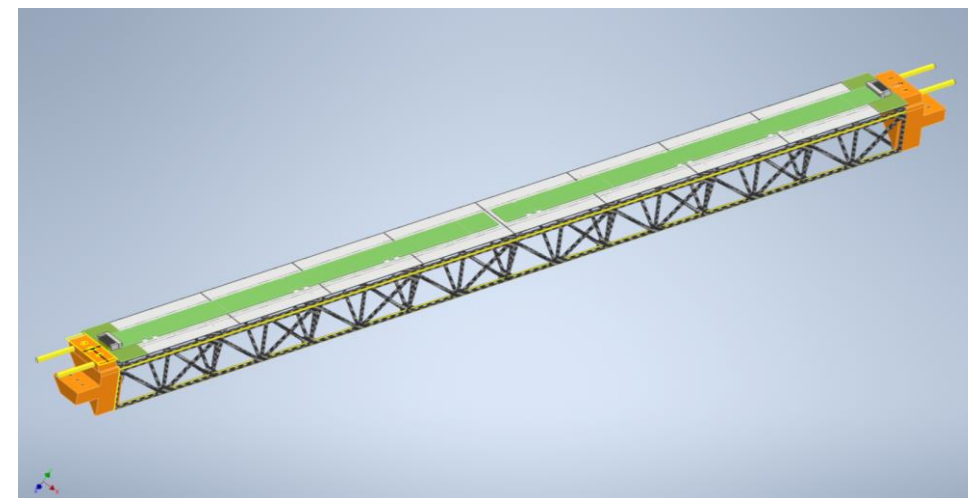
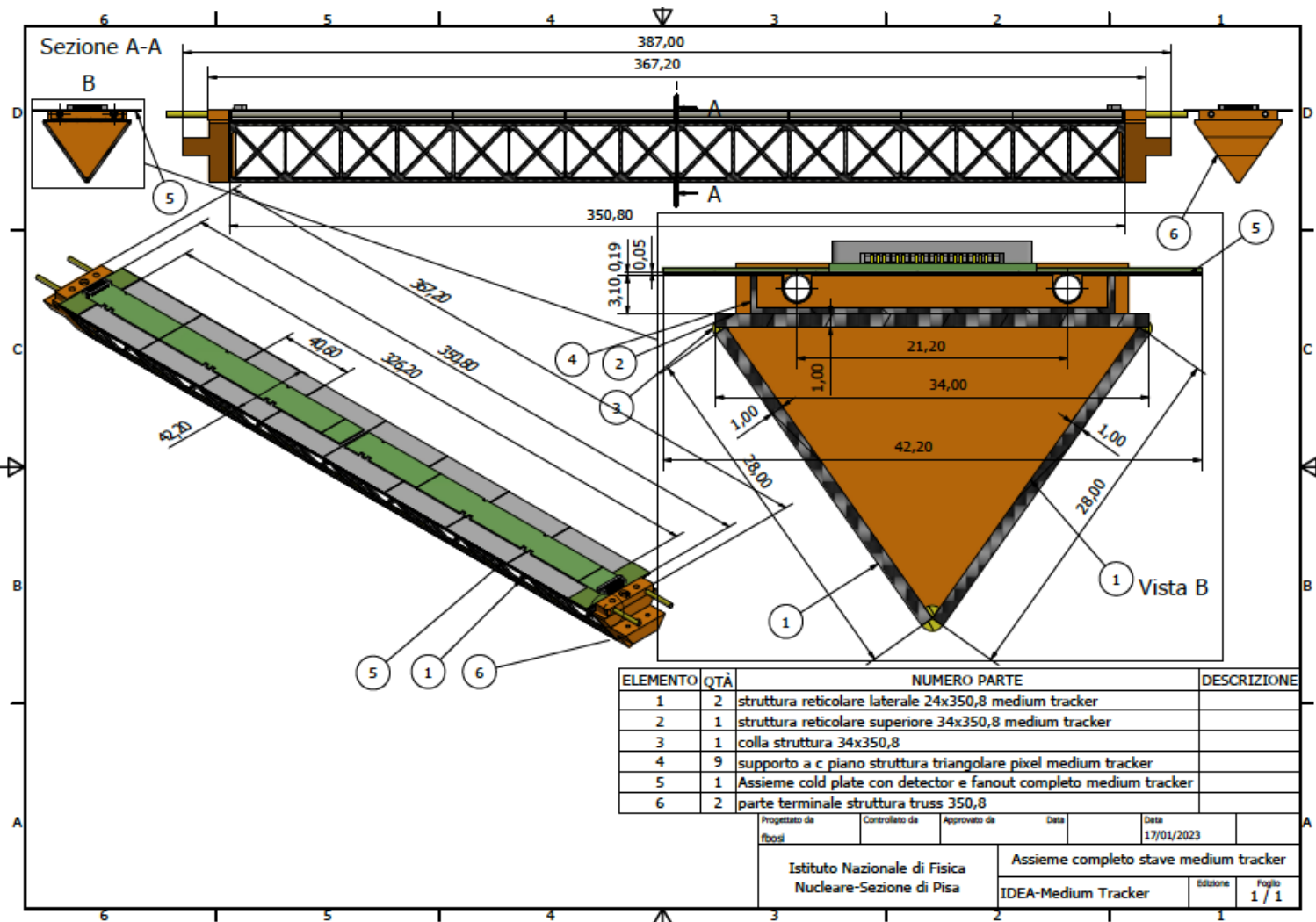
**Power budget**  
**~342 W**

Total weight ~1 kg  
 Water cooled (2 pipes of 2 mm diameter)

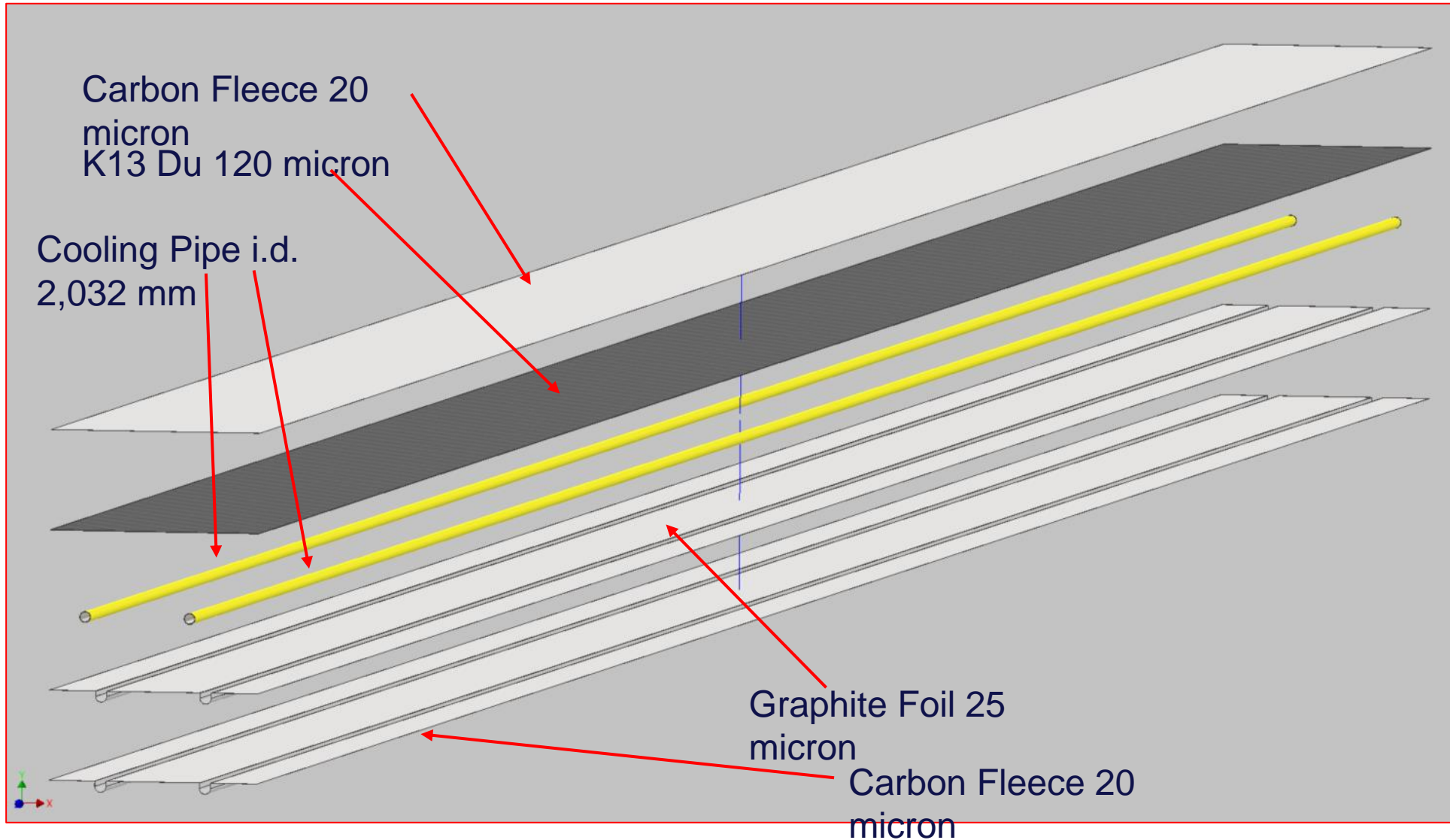
# MIDDLE TRACKER



# Stave detail



# Detail of the cold plate

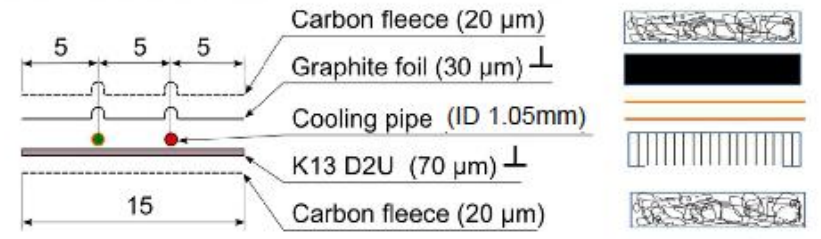


# SINGLE STRUCTURE COLD PLATE

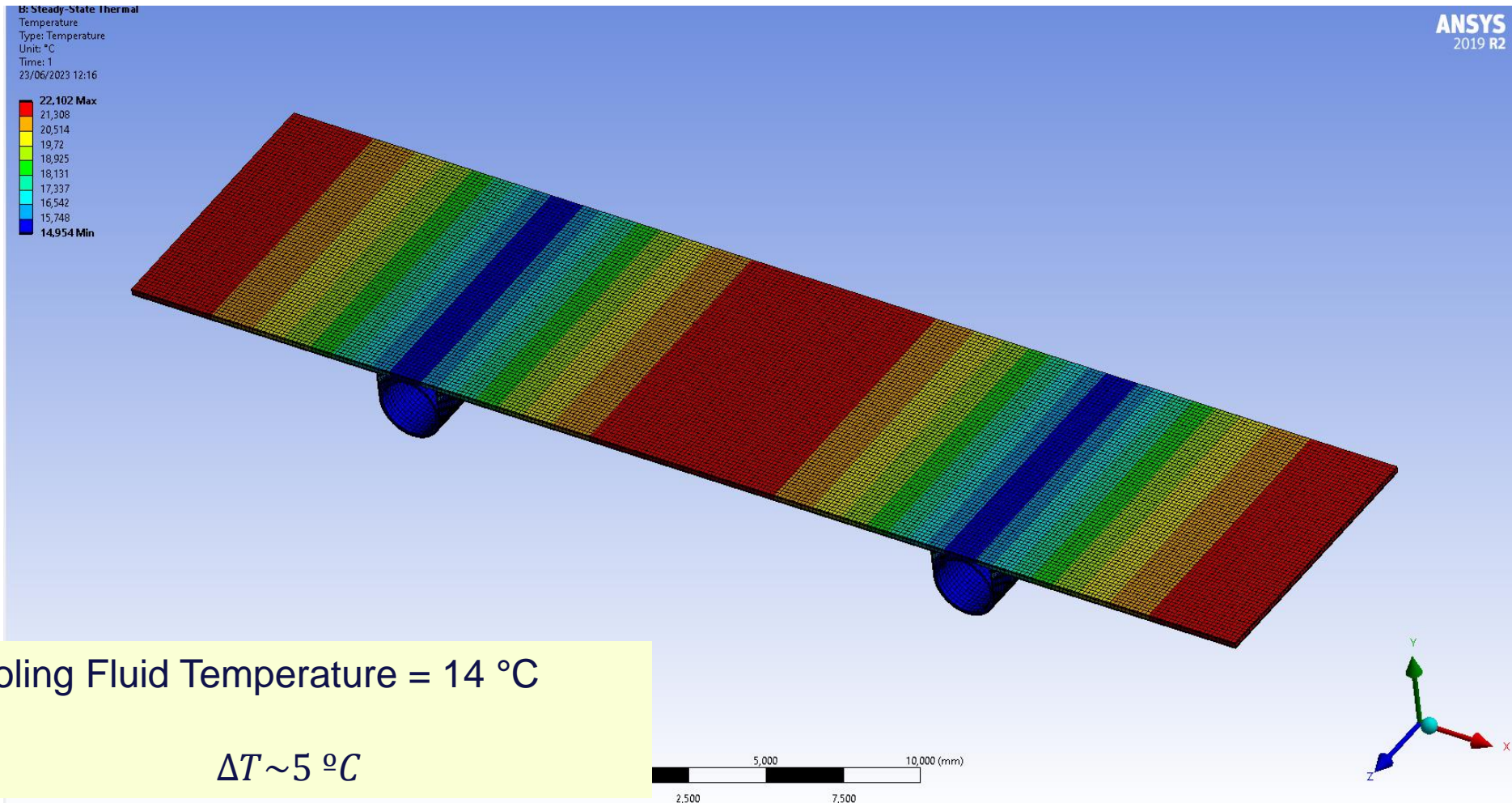


## Production Process: **Manual Lay-up**

New innovative design developed fo ALICE ITS Upgrade



PROTOTYPE REALIZED BY ALICE



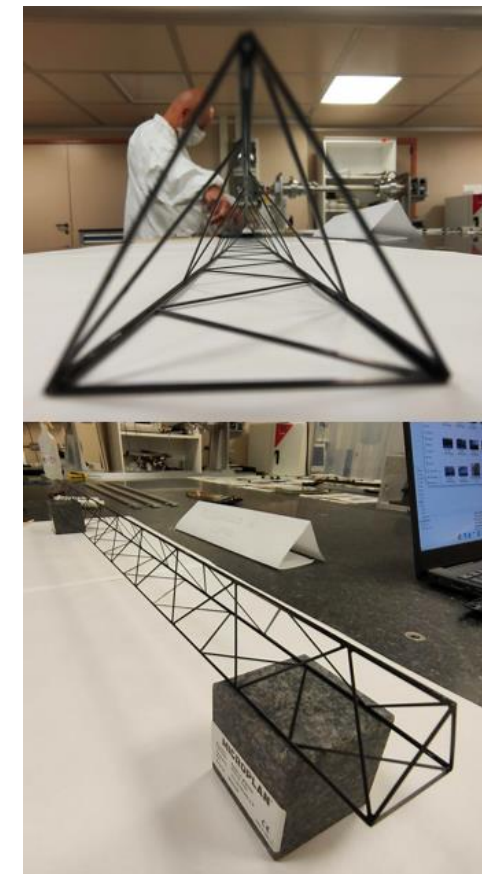
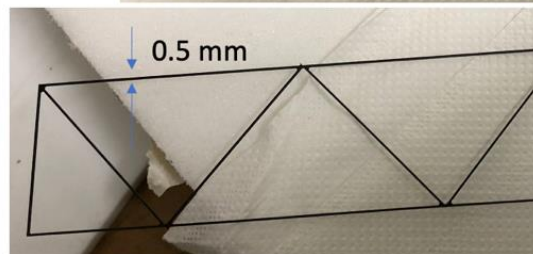
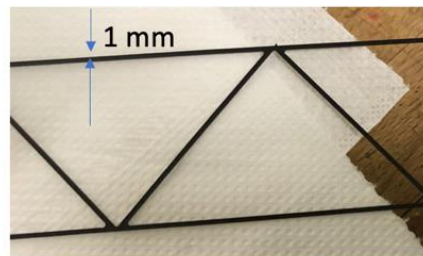
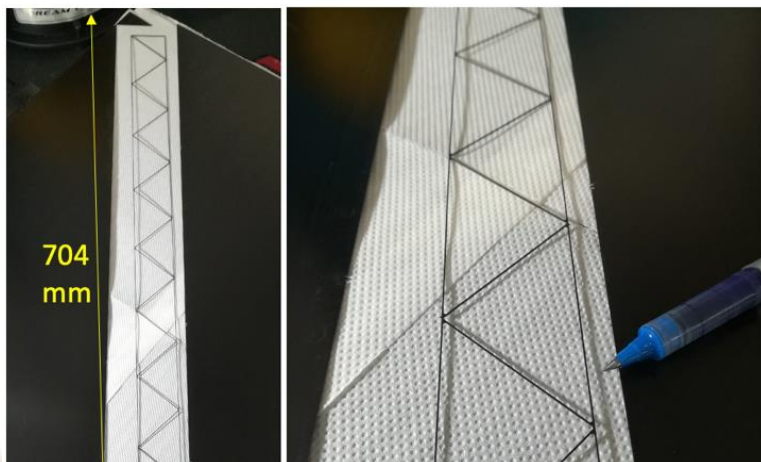
Cooling Fluid Temperature = 14 °C

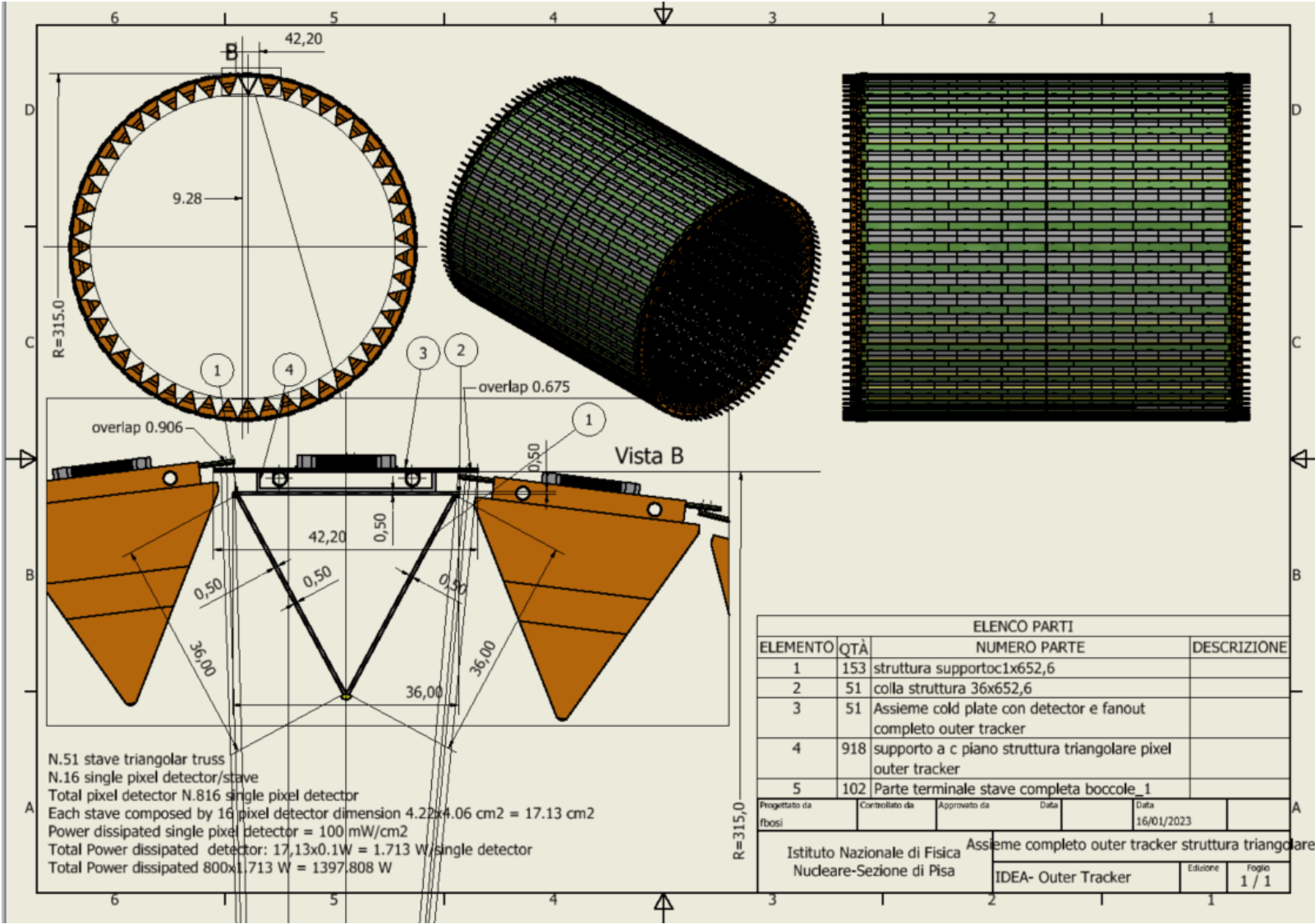
$\Delta T \sim 5 \text{ }^\circ\text{C}$



# Prototypes built for Belle II upgrade in Pisa

CF water-jet cut (by WatAJet Company)





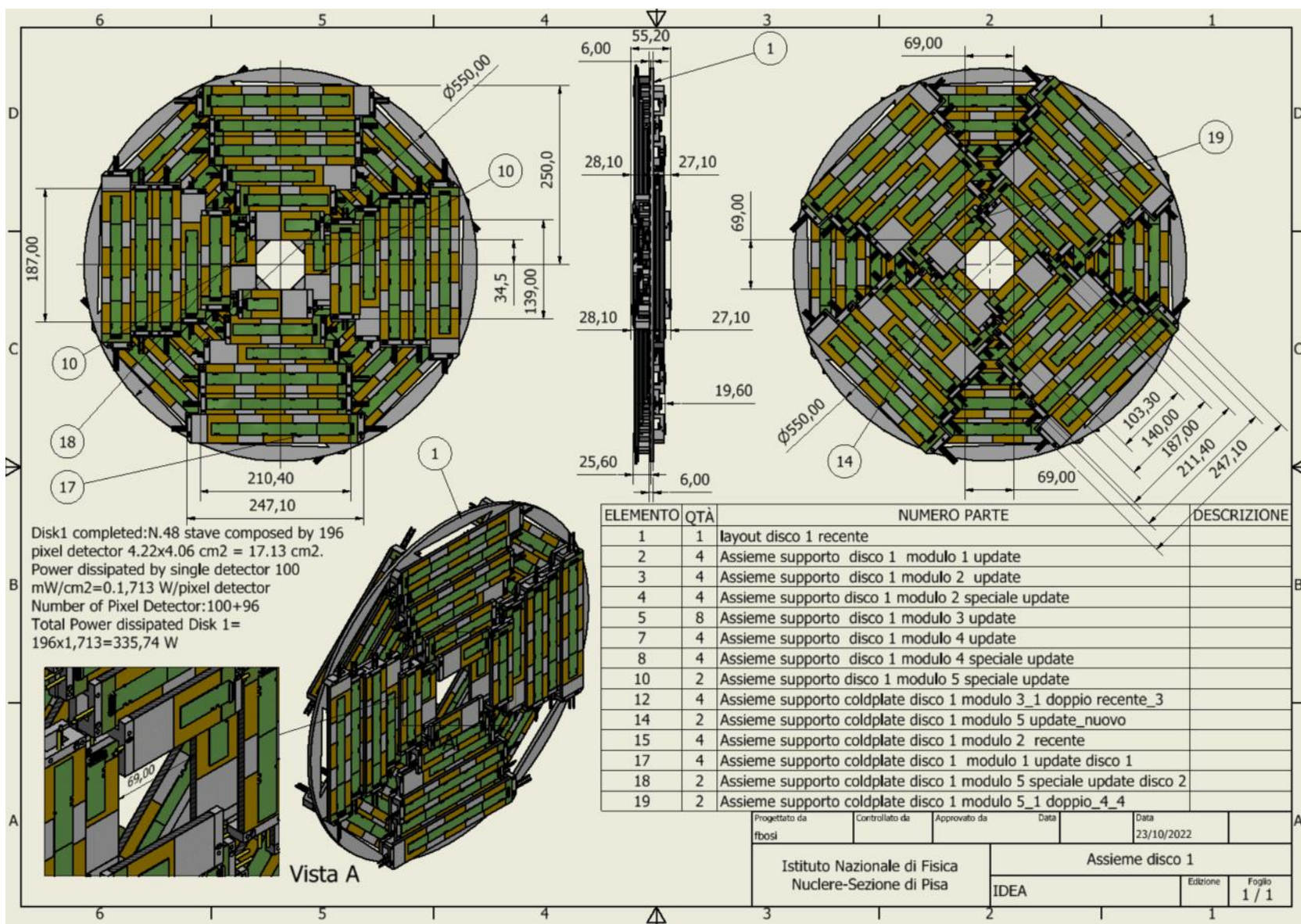
**Outer Vertex Tracker Barrel**  
**At 31.5 cm radius**

51 staves of 16 modules each

Lightweight reticular support structure (ALICE/Belle-II like)

Total weight ~3.7 kg  
 Readout chips either side  
**Power budget ~1400 W**

Water cooled (2 pipes of 2 mm diameter)



**Outer Vertex Tracker Disk 1**  
 2 sides (front and back) each with 4 petals.

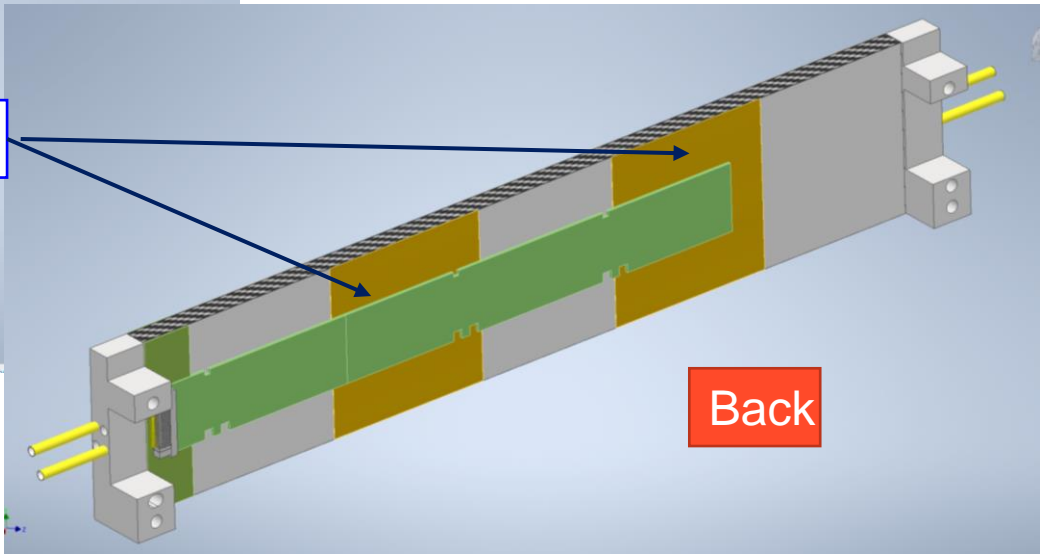
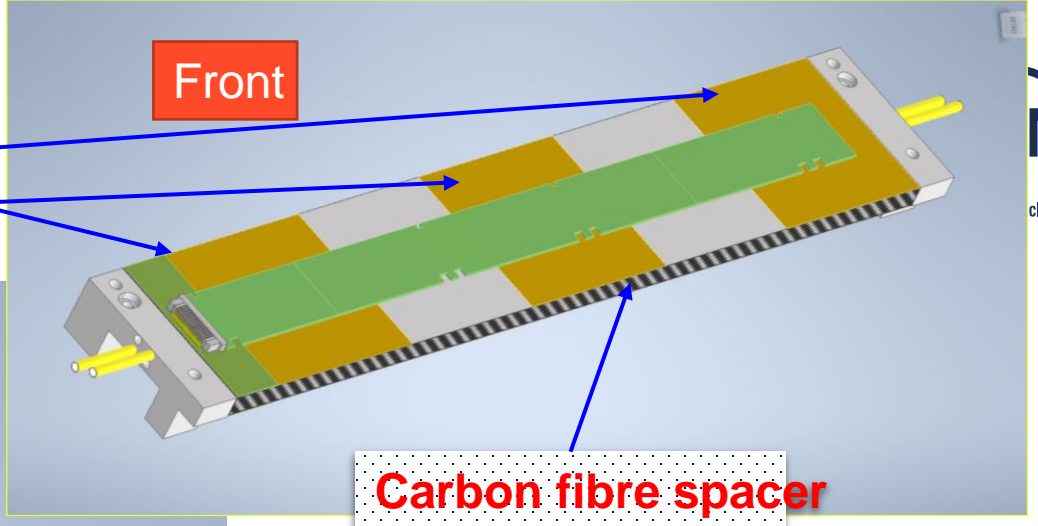
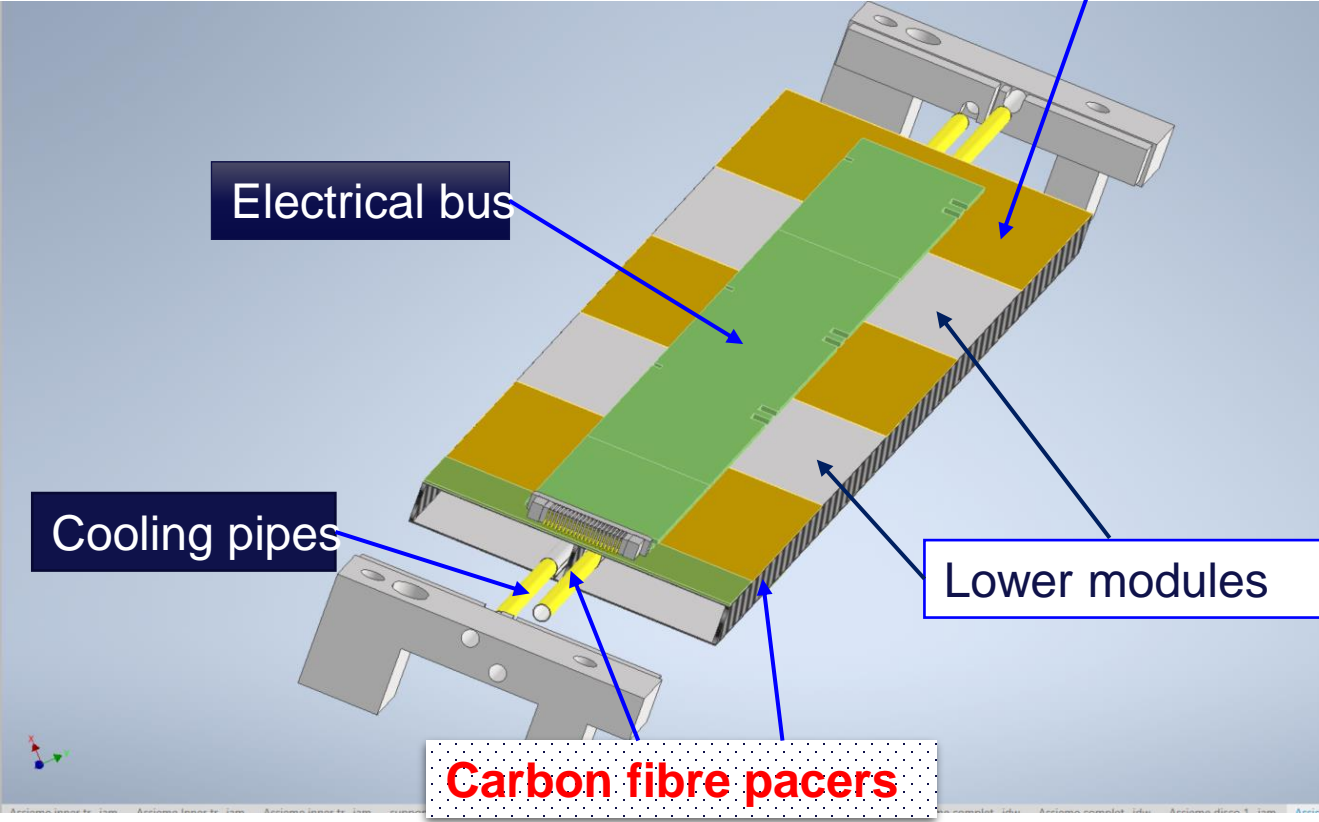
One petal is made of different staves of overlapping modules

Total modules per disk: 196  
 Total weight ~850 grams  
 Power budget ~ 336 W

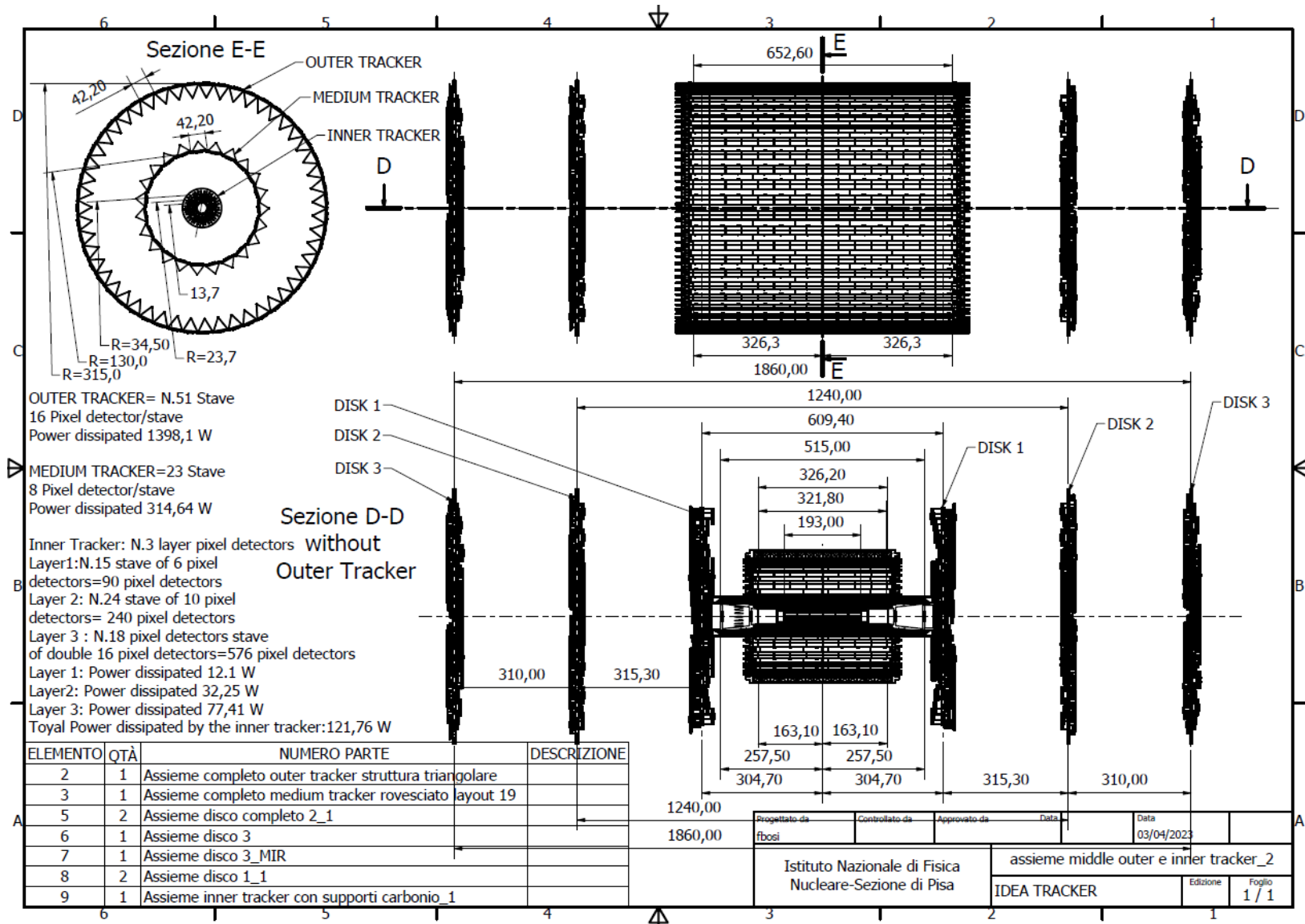
Cooling using 1 water pipe (2 mm diameter)

Similar geometry for the other two disks

# Typical disk module stave



# Overall layout and dimensions



# Material budget estimate

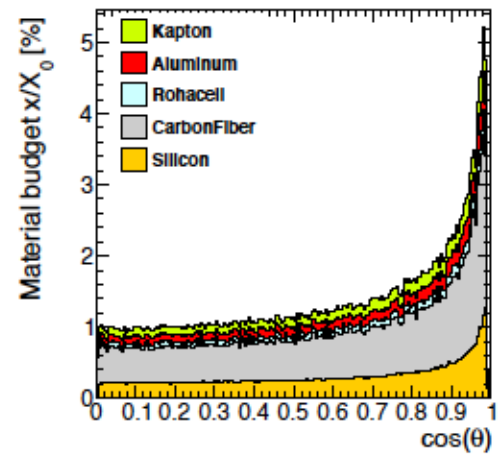
- Detailed table with materials from the CAD drawings
- Material smeared over the surface of the ladder

	COMPONENT	QUANTITY	STAVE QUANTITY	VOLUME from CAD mm3	TOTAL STAVE VOLUME mm3	DENSITY g/cm3	SINGLE STAVE WEIGHT g	TOTAL WEIGHT g	SURFACE TO SPREAD THE VOLUME cm2	THICKNESS EQUIVALENT cm	MATERIAL RADIATION LENGHT	EQUIVALENT RADIATION LENGTH	
Layer 1	BUS KAPTON	4	15	34,668	138,672	1,42	0,197	2,954	15,826	0,00876229	28,41	0,031	
	BUS ALUMINUM	4	15	8,667	34,668	2,7	0,094	1,404	15,826	0,002190572	8,90	0,025	
	COSTOLA CARBON FIBER	2	15	144	288,000	1,85	0,533	7,992	15,826	0,018197902	26,00	0,070	
	COSTOLA ROHACELL	1	15	720,425	720,425	0,071	0,051	0,767	15,826	0,04552161	563,00	0,008	
	LAMINA APPOGGIO CARBON FIBER	1	15	169,84	169,840	1,85	0,314	4,713	15,826	0,010731707	26,00	0,041	
	DETECTORS	6	15	13,44	80,640	2,33	0,188	2,818	15,826	0,005095413	9,70	0,053	
	GLUE	1	15	113,484	113,484	1,12	0,127	1,907	15,826	0,007170732	33,50	0,021	
	TOTAL SINGLE STAVE LAYER 1						1,504						0,249
	TOTAL LAYER 1			12				17,832					

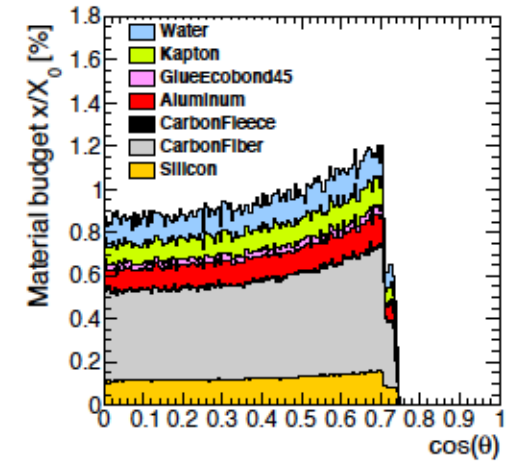
# Material budget estimate from CAD

- Detailed table with materials from the CAD drawings
  - Material smeared over the surface of the ladder
  - **Inner vertex 0.25% radiation length per ladder:**
    - Due to ~40% overlap between two staves, the average material budget per layer increases to 0.35%
  - **Outer vertex**
    - 0.71 % middle
    - 0.58% outer
- Needs inputs from Physics if middle vertex at 13 cm is needed for low momentum tracks or not

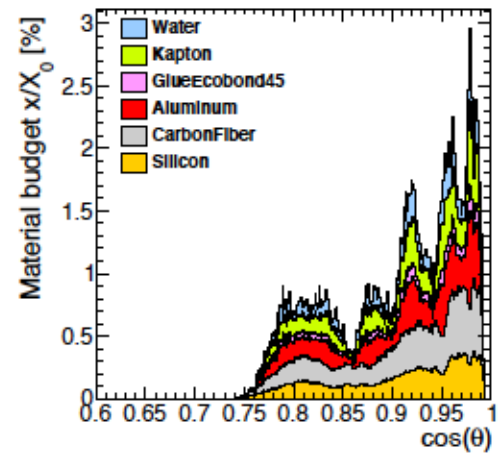
# Simulated material budget



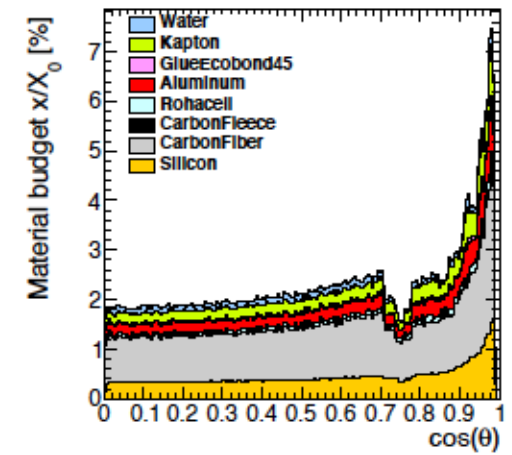
(a) Vertex inner barrel



(b) Vertex outer barrel



(c) Vertex disks



(d) Whole vertex detector

See talk from A. Ilg

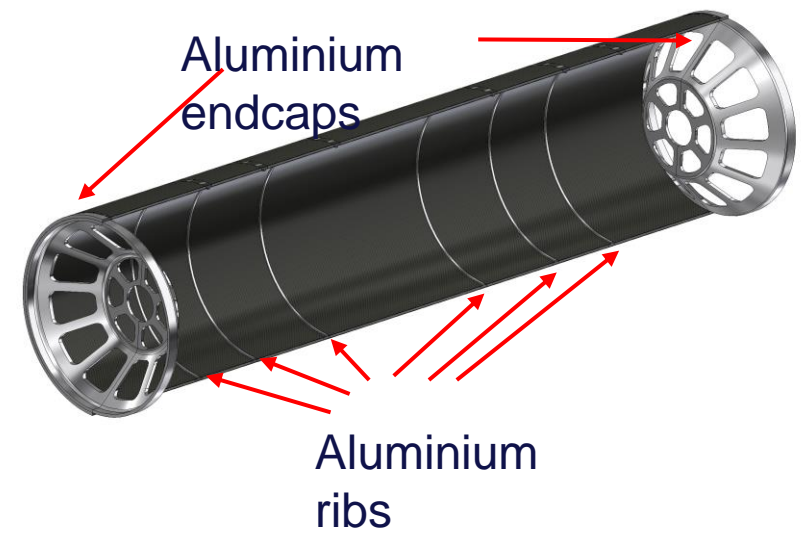
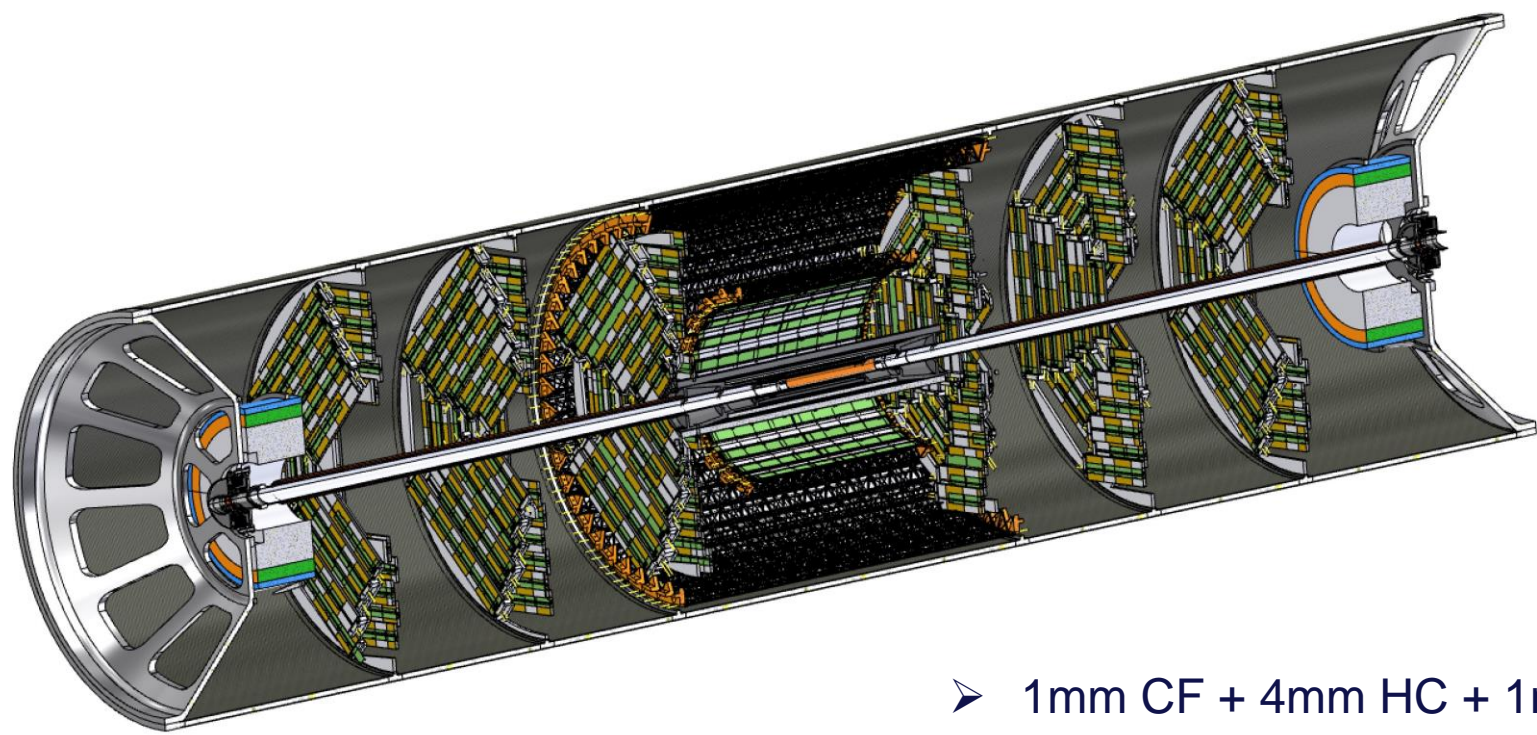


# Support cylinder

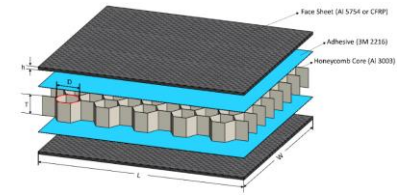


All elements in the interaction region (Vertex and LumiCal) are mounted rigidly on a support cylinder that guarantees mechanical stability and alignment

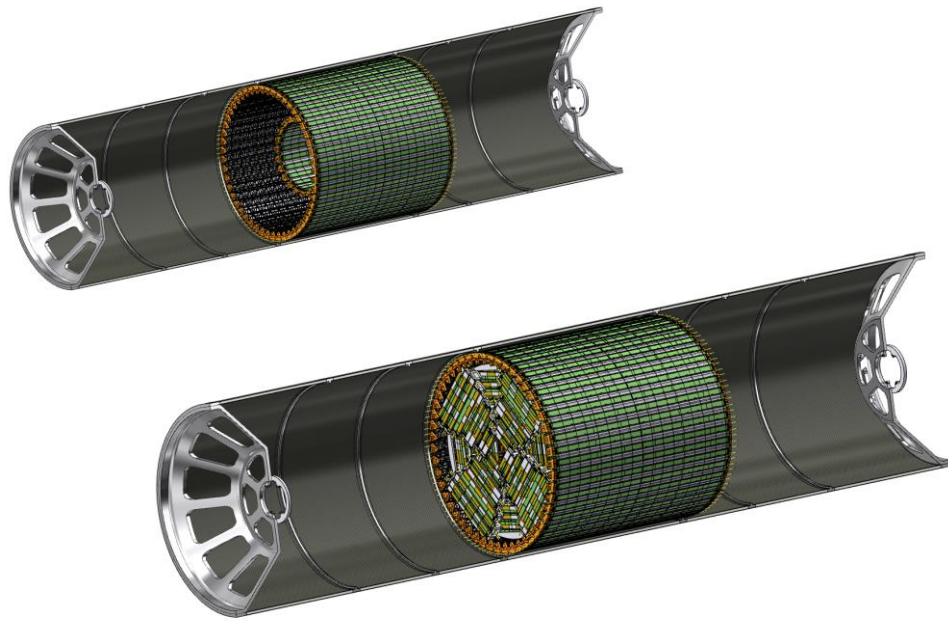
- Once the structure is assembled it is slid inside the rest of the detector
- Studies on-going where to anchor it (most likely to the Calorimeter)



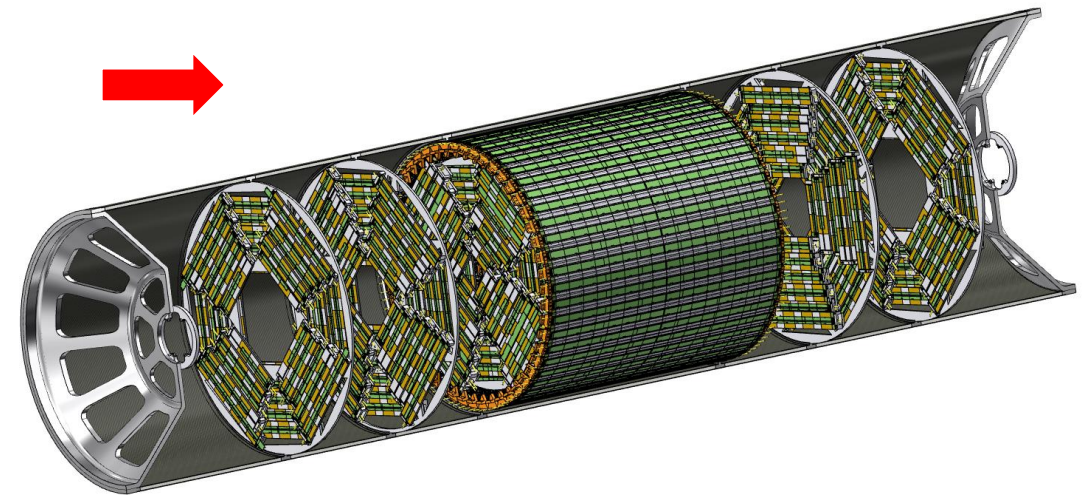
➤ 1mm CF + 4mm HC + 1mm CF



# Assembly procedure – I

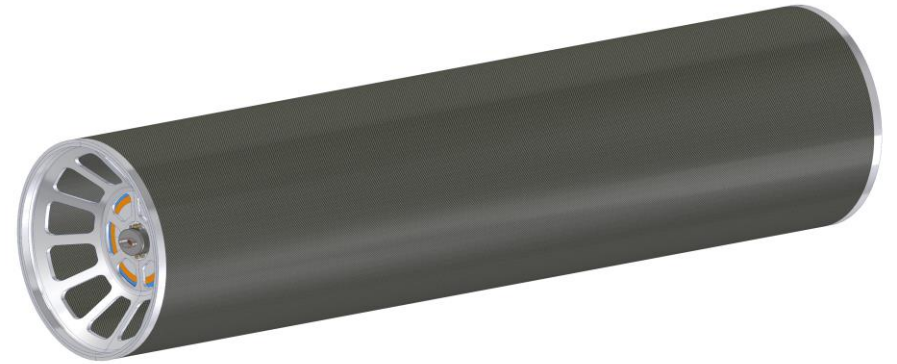
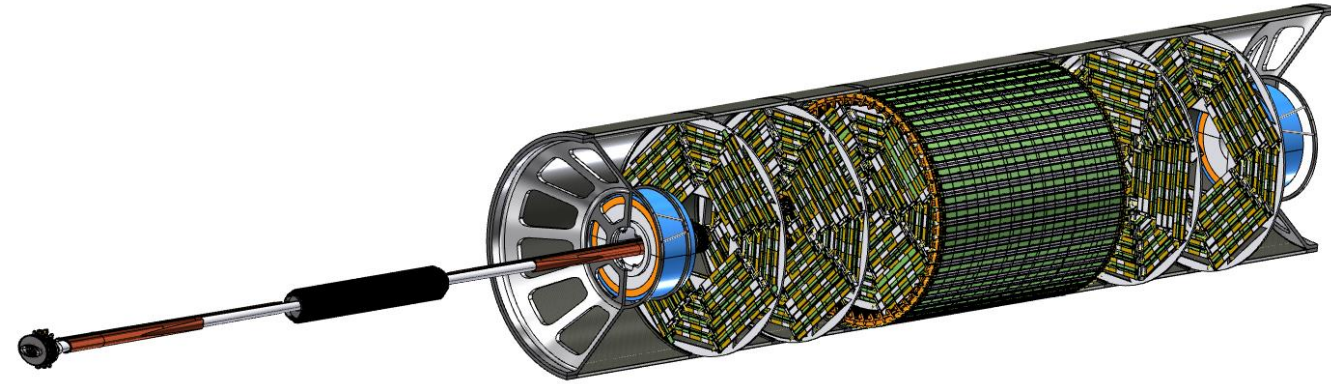


1) Outer vertex tracker, middle vertex tracker and disks 1 are installed as a rigid structure inside the support tube



2) Disks 2 and 3 are installed inside the support tube

# Assembly procedure – II



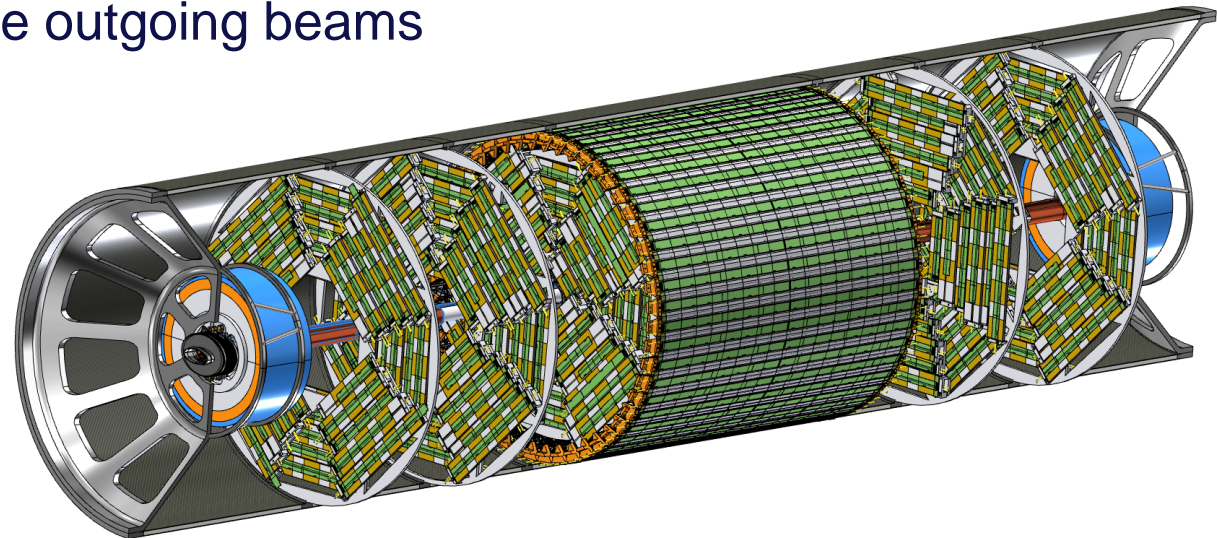
3) LumiCal is installed in centered position, then beam pipe with inner vertex detector is inserted with a dedicated tool inside disks and outer vertex tracker, then fixed to both endcaps



4) LumiCal can be aligned in the correct position on the outgoing beams

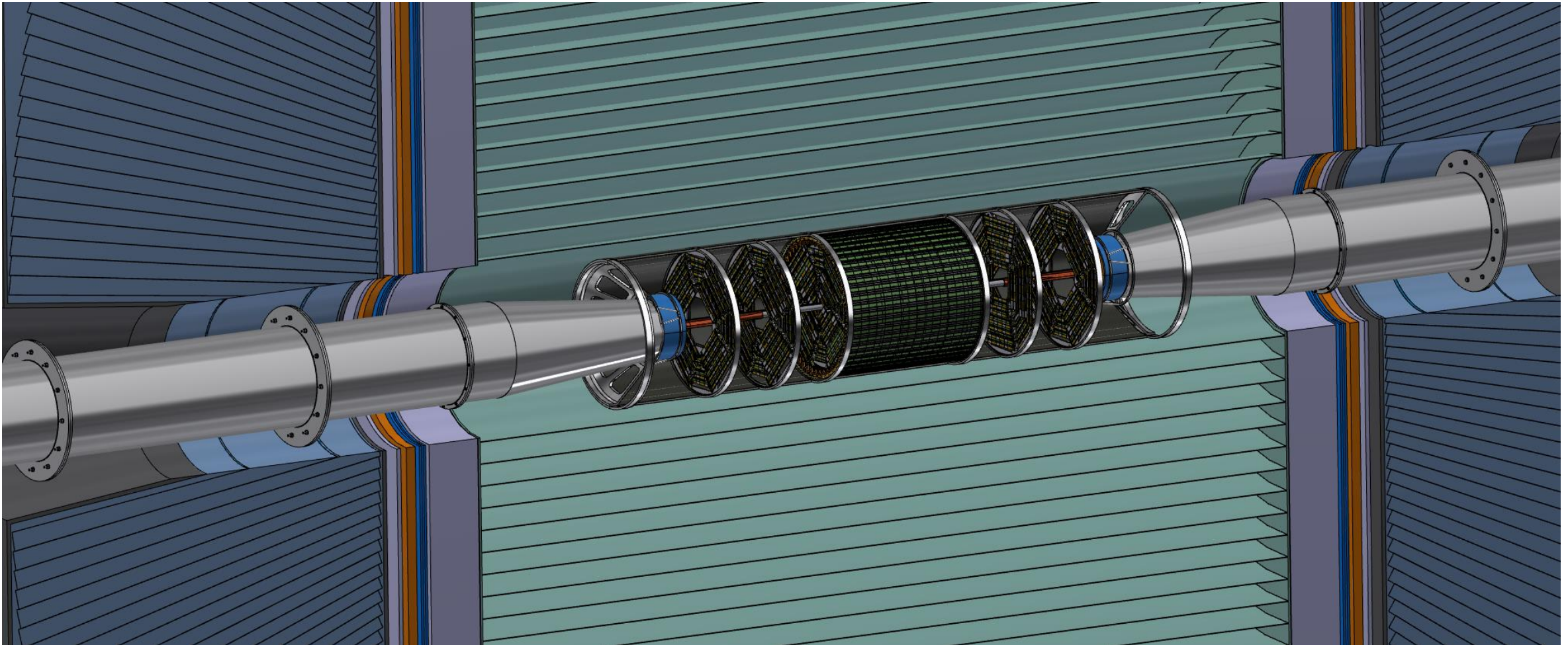


5) Support tube can be closed



# General integration

*M. Boscolo, F. Palla, F. Franesini, F. Bosi and S. Lauciani, Mechanical model for the FCC-ee MDI, EPJ Techn Instrum* **10**, 16 (2023).  
<https://doi.org/10.1140/epjti/s40485-023-00103-7>



# Conclusions



**A layout of the interaction region with LumiCal and vertex trackers of the IDEA detector has been engineered**

- Feasibility studies of integration successfully done including mounting sequence
- Documented in
  - *M. Boscolo, F. Palla, F. Franesini, F. Bosi and S. Lauciani, Mechanical model for the FCC-ee MDI, EPJ Techn Instrum 10, 16 (2023). <https://doi.org/10.1140/epjti/s40485-023-00103-7>*
  - *MDI Note for mid-term review (Version 1) <https://cernbox.cern.ch/s/FQEHOkF9kTeBsBh>*

## **Next/ongoing steps:**

- **Inner Vertex detector**
  - Study thermal isolation from the beampipe bakeout in progress
  - Study the routing of the services (readout and power cables) in progress
- **Outer Vertex Tracker**
  - Study the routing of the services (readout and power cables, cooling manifolds) in progress

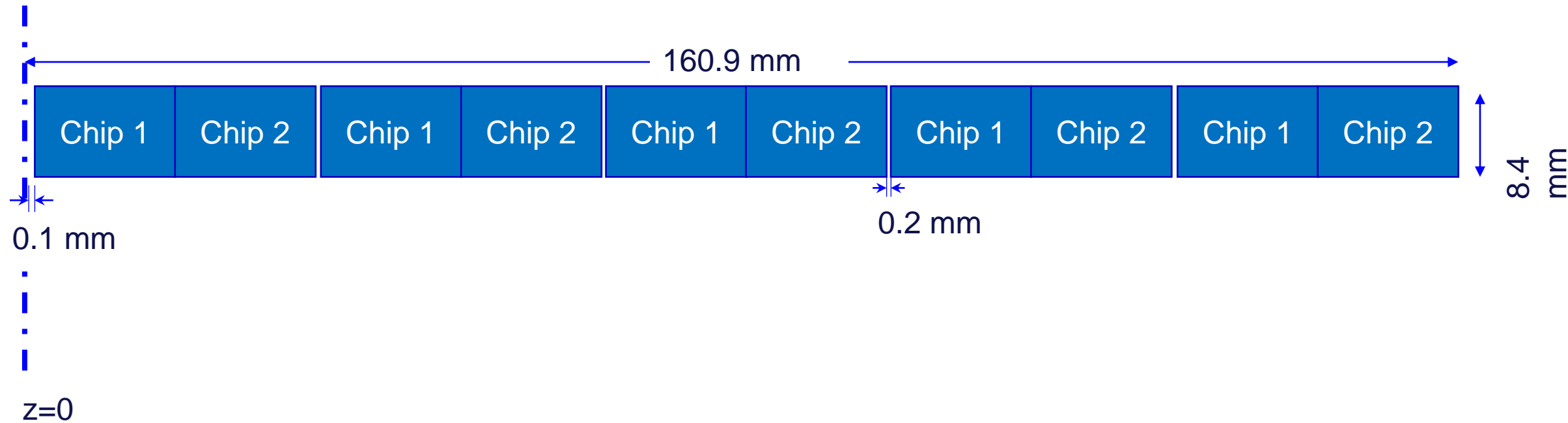


Thank you  
for your attention.



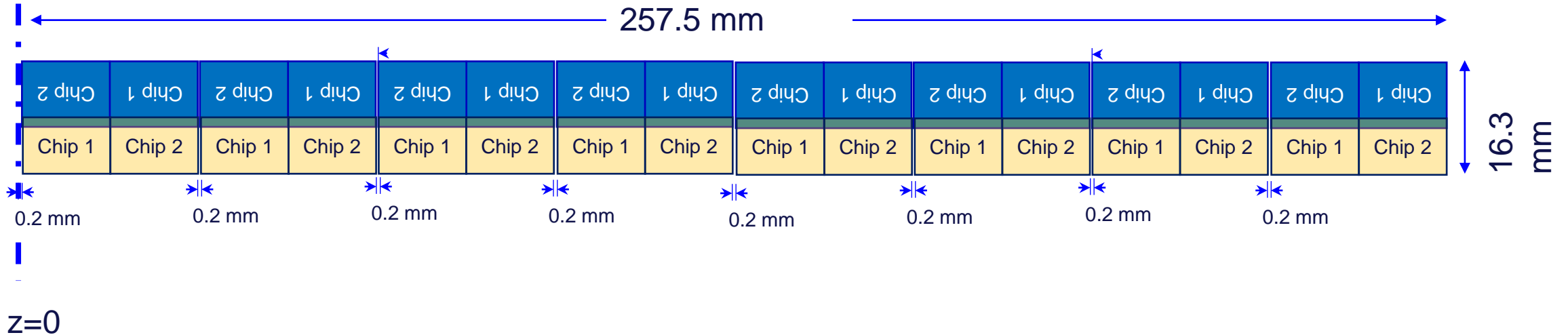
Backup

# Half-ladder layout – layer 2



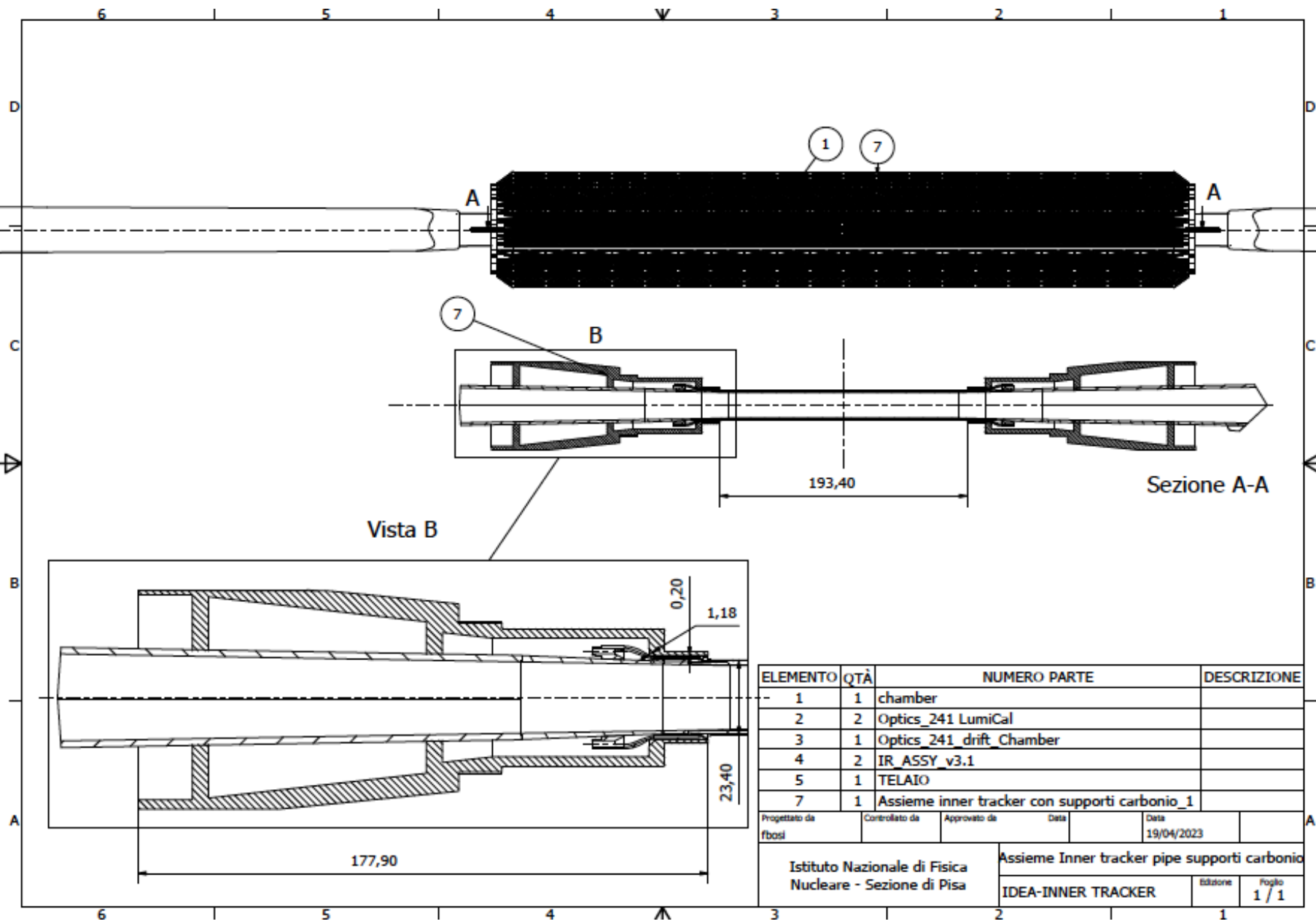


# Half ladder layout – layer 3

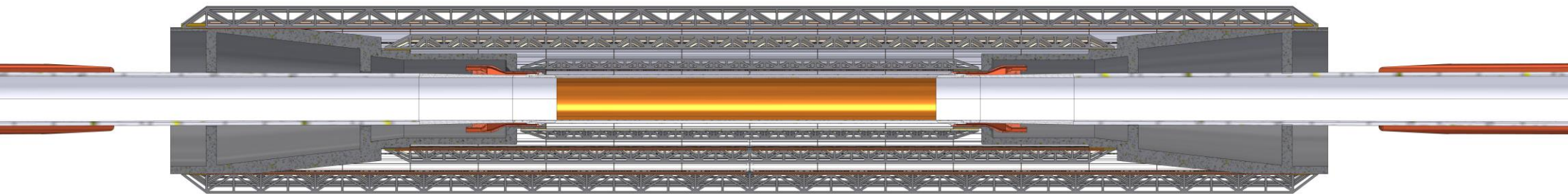


Overlapping in  $r - \varphi:2$  parallel ladders separated by  $500 \mu\text{m}$   
 - see engineering drawings later

Passive parts on the sides



# Vertex on the beam-pipe



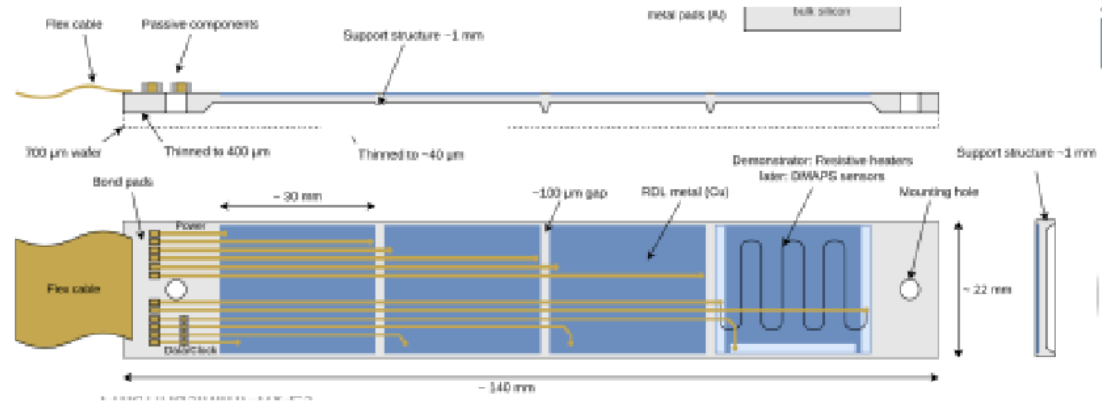
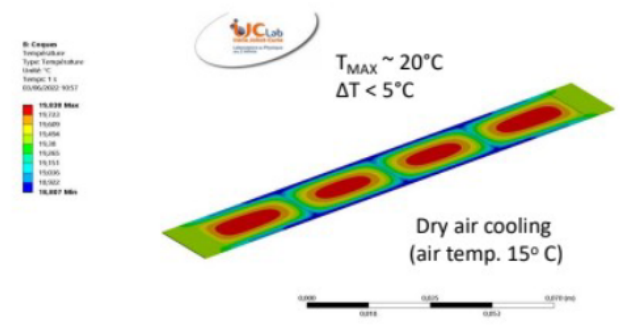
# Air cooling for Belle-II upgrade

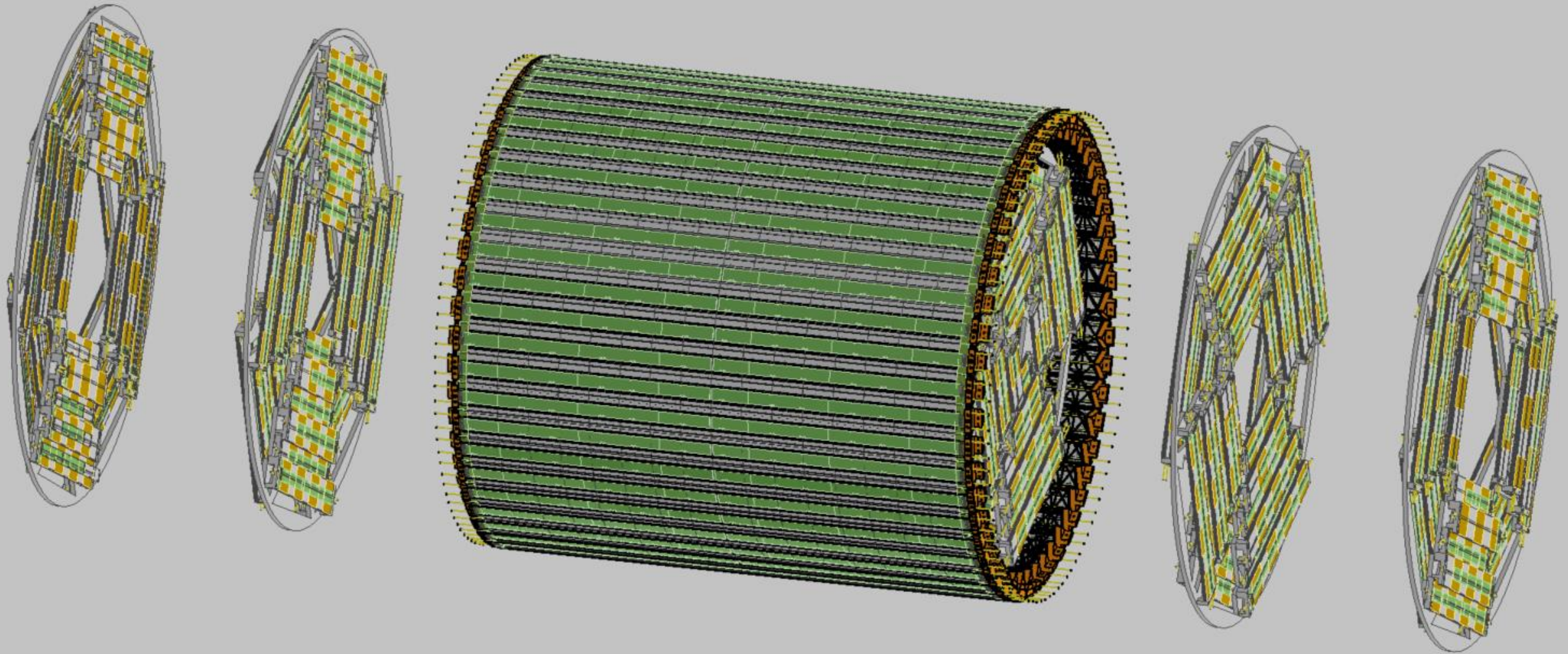


WP10.2

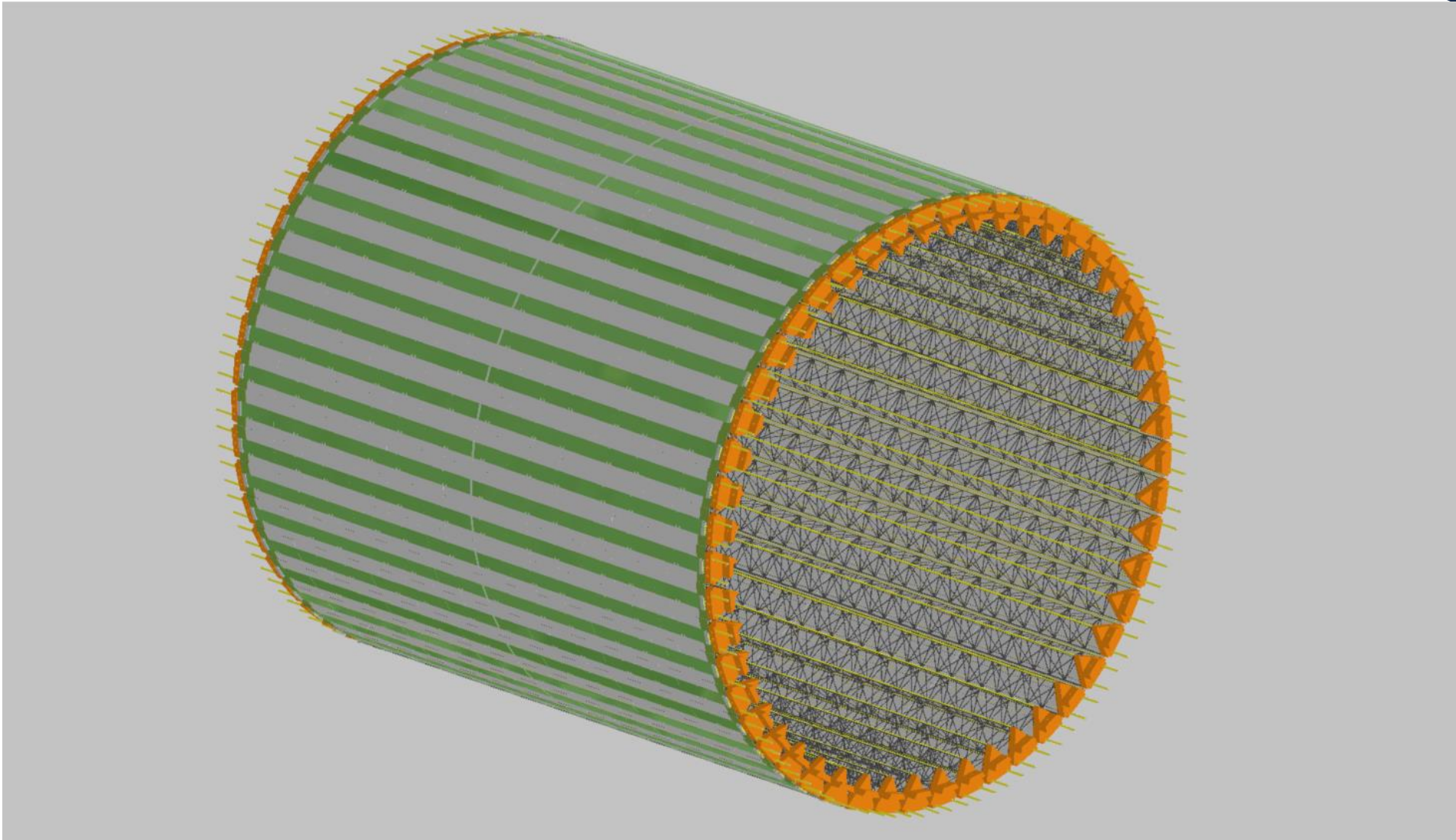
Integrated micro-channels

Thin multi-CMOS-chip Silicon structures for Belle 2 upgrade  
 Thermo-mechanical demonstrator submitted to IZM by Valencia and Bonn, thermal simulations in IJCLab Paris

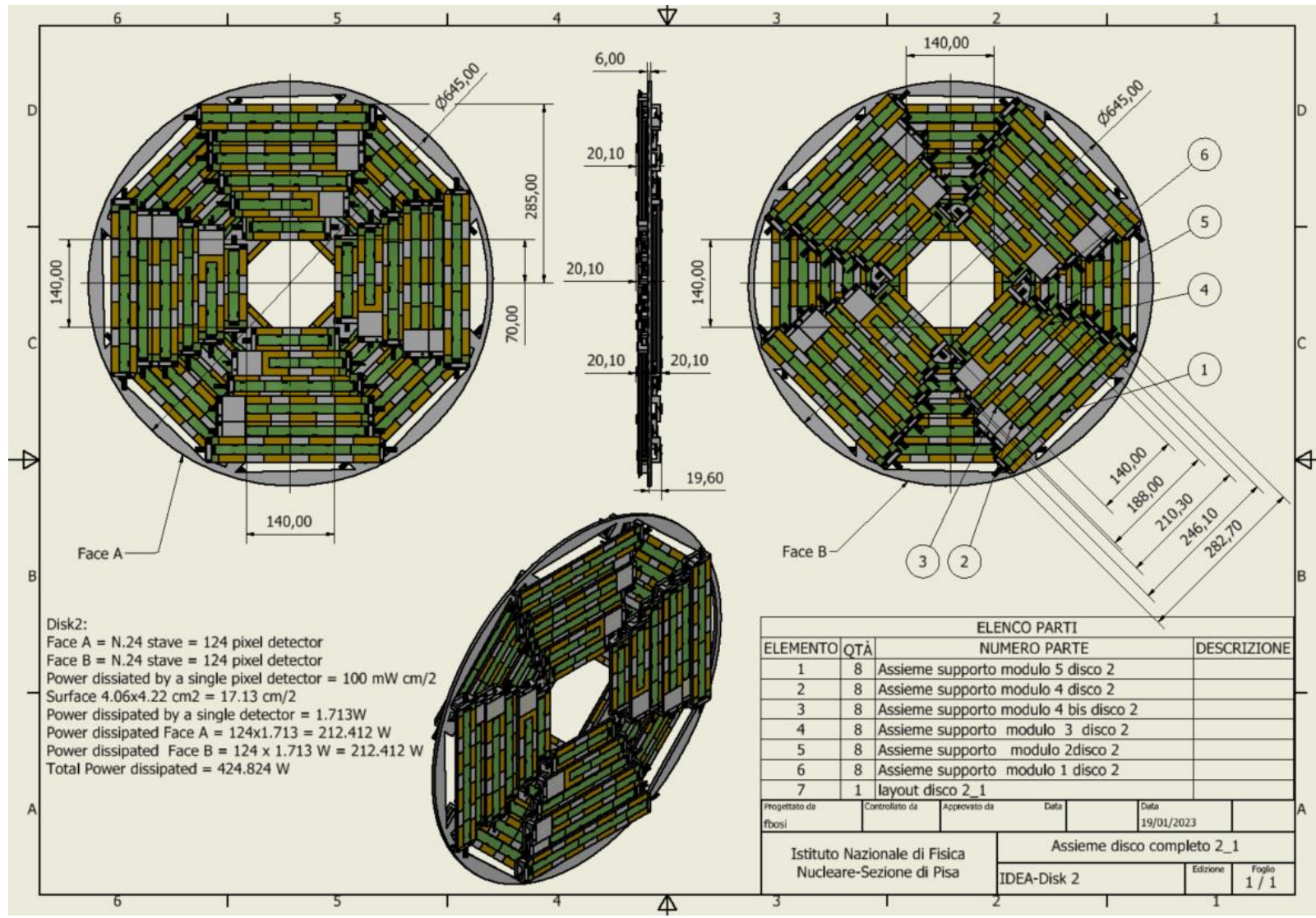




# OUTER TRACKER



# DISK 2



# DISK 3

